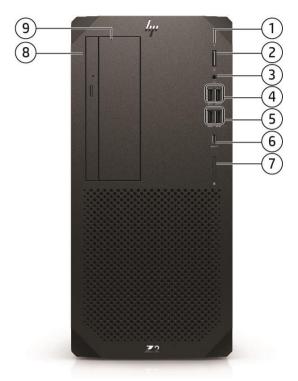
Overview

HP Z2 G9 Tower Workstation Desktop PC



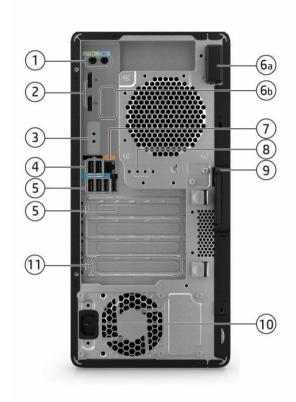
front

- 1. HDD Activity LED
- 2. Power button
- 3. Universal audio jack (with CTIA & OMTP headset support)
- 4. (2) USB-A 10Gbps ports (1 charge port supports up to 5V/2.1A)
- 5. (2) USB-A 10Gbps rate ports

- 6. (1) USB-C® 20Gbps port (optional, charge supports up to 5V/3A)
- 7. SD card reader 4.0 (optional)
- 8. Slim ODD bay
- 9. External 5.25" bay



Overview



rear

- 1. (1) Audio Line-in jack
 - (1) Audio Line-out jack
- 2. (2) DisplayPort 1.4 ports
- 3. Flex I/O module: choose one from the following:
 (1) DisplayPort 1.4, (1) HDMI 2.0b, (1) VGA, (1) Dual USBA 5Gbps port, (1) USB-C® 10Gbps port (Power Delivery 15W,
 Alt Mode DisplayPort), (1) 2nd 1 GbE LAN, (1) Thunderbolt 3
 with USB-C® / USB4 40Gbps * (cabled to PCIe AIC**) (1) 1Gbps
 Fiber LC NIC
- 4. (2) Hi-Speed USB-A 480Mbps port
- 5. (2) USB-A 10Gbps ports
 - (1) USB-A 5Gbps port
 - (1) Hi-Speed USB-A 480Mbps port
- *Maximum speed requires DisplayPort™ and PCIe aggregation.
- **Thunderbolt support only in PCI-E slot4.

NOTE: Onboard Display support DP1.4/HBR2. Flex I/O module Display support DP1.4/HBR3. Resolution all support up to 5120x3200 24bpp @60Hz.

Form Factor

Tower

Operating Systems

Preinstalled:

- Windows 11 Pro HP recommends Windows 11 Pro²
- Windows 11 Home HP recommends Windows 11 Pro²
- Windows 10 Pro (available through downgrade rights from Windows 11 Pro) 1,2,3
- Linux®-ready⁵

- 6. (1) WLAN Antenna (optional)
 - a. Internal
 - b. External
- 7. (1) 1Gb LAN
- 8. 2nd serial port (optional)
- 9. Hood lock (optional)
- 10. Power connector

Overview

- Ubuntu^{®4,5}
 - Intel 12th generation processors will support and preinstall Ubuntu 20.02 and 20.04.
 - Intel 13th generation processors support and preinstall Ubuntu 22.04 LTS

Web-supported only:

Windows 10 Enterprise 64²

Supported Version:

- HP tested Windows 10, versions 20H2, 21H1, 21H2 and 22H2 on this platform. For testing
 information on newer versions of Windows 10, please see:
 https://support.hp.com/document/c05195282.
- Red Hat[®] Enterprise Linux[®] Workstation 8⁶
- SUSE Linux® Enterprise Desktop 156
- Ubuntu^{®4,5}
 - Intel 12th generation processors will support and preinstall Ubuntu 20.02 and 20.04.
 - Intel 13th generation processors support and preinstall Ubuntu 22.04 LTS
- ¹ Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).
- ² Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.
- ³This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.
- ⁴ Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply and additional requirements may apply over time for updates.
- ⁵A certified preloaded version of Ubuntu® 20.04 LTS is available from HP for this platform. Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply, and additional requirements may apply over time for upgrades.

⁶For detailed Linux[®] OS/hardware support information, see: http://www.hp.com/support/linux_hardware_matrix

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282

Processors Overview^{1,3,4,5}

Intel 14th Generation Processors:

Intel® Core™ i5-14400 (2.5GHz P-Core base frequency, 1.8GHz E-Core base frequency, up to 3.5GHz E-Core Max Turbo frequency, up to 4.7 GHz P-core Max Turbo frequency, 20MB L3 cache, 6 P-cores and 4 E-cores, 16 threads)



Overview

Intel® Core™ i5-14500 (2.6GHz P-Core base frequency, 1.9GHz E-Core base frequency, up to 3.7GHz E-Core Max Turbo frequency, up to 5GHz P-core Max Turbo frequency, 24MB L3 cache, 6 P-cores and 8 E-cores, 20 threads)

Intel® Core™ i5-14600 (2.7GHz P-Core base frequency, 2GHz E-Core base frequency, up to 3.9GHz E-Core Max Turbo frequency, up to 5.2GHz P-core Max Turbo frequency, 24MB L3 cache, 6 P-cores and 8 E-cores, 20 threads)

Intel® Core™ i5-14600K (3.5GHz P-Core base frequency, 2.6GHz E-Core base frequency, up to 4.2GHz E-Core Max Turbo frequency, up to 5.3GHz P-core Max Turbo frequency, 24MB L3 cache, 6 P-cores and 8 E-cores, 20 threads)

Intel® Core™ i7-14700 (2.1GHz P-Core base frequency, 1.5GHz E-Core base frequency, up to 4.2Ghz E-Core base frequency, up to 5.3Ghz E-Core base frequency, 33MB L3 cache, 8 P-cores and 12 E-cores, 28 threads)

Intel® Core™ i7-14700K (3.4GHz P-Core base frequency, 2.5GHz E-Core base frequency, up to 4.3GHz E-Core Max Turbo frequency, up to 5.5 GHz P-core Max Turbo frequency, 33MB L3 cache, 8 P-cores and 12 E-cores, 28 threads)

Intel® Core™ i9-14900 (2GHz P-Core base frequency, 1.5GHz E-Core base frequency, up to 4.3GHz E-Core Max Turbo frequency, up to 5.4 GHz P-core Max Turbo frequency, 36MB L3 cache, 8 P-cores and 16 E-cores, 32 threads)

Intel® Core™ i9-14900K (3.2GHz P-Core base frequency, 2.4GHz E-Core base frequency, up to 4.4GHz E-Core Max Turbo frequency, up to 5.6 GHz P-core Max Turbo frequency, 36MB L3 cache, 8 P-cores and 16 E-cores, 32 threads)

Intel 13th Generation Processors:

Intel® Core™ i5-13400 (2.5GHz P-Core base frequency, 1.8GHz E-Core base frequency, up to 3.3GHz E-Core Max Turbo frequency, up to 4.6 GHz P-core Max Turbo frequency, 20MB L3 cache, 6 P-cores and 4 E-cores, 16 threads)

Intel® Core™ i5-13500 (2.5GHz P-Core base frequency, 1.8GHz E-Core base frequency, up to 3.5GHz E-Core Max Turbo frequency, up to 4.8 GHz P-core Max Turbo frequency, 24MB L3 cache, 6 P-cores and 8 E-cores, 20 threads)

Intel® Core™ i5-13600 (2.7GHz P-Core base frequency, 2GHz E-Core base frequency, up to 3.7GHz E-Core Max Turbo frequency, up to 5 GHz P-core Max Turbo frequency, 24MB L3 cache, 6 P-cores and 8 E-cores, 20 threads)

Intel® Core™ i5-13600K (3.5GHz P-Core base frequency, 2.6GHz E-Core base frequency, up to 3.9GHz E-Core Max Turbo frequency, up to 5.1 GHz P-core Max Turbo frequency, 24MB L3 cache, 6 P-cores and 8 E-cores, 20 threads)

Intel® Core™ i7-13700 (2.1GHz P-Core base frequency, 1.5GHz E-Core base frequency, up to 4.1Ghz E-Core base frequency, up to 5.1Ghz E-Core base frequency, 30MB L3 cache, 8 P-cores and 8 E-cores, 24 threads)

Intel® Core™ i7-13700K (3.4GHz P-Core base frequency, 2.5GHz E-Core base frequency, up to 4.2GHz E-Core Max Turbo frequency, up to 5.3 GHz P-core Max Turbo frequency, 30MB L3 cache, 8 P-cores and 8 E-cores, 24 threads)

Intel® Core™ i9-13900 (2GHz P-Core base frequency, 1.5GHz E-Core base frequency, up to 4.2GHz E-Core Max Turbo frequency, up to 5.2 GHz P-core Max Turbo frequency, 36MB L3 cache, 8 P-cores and 16 E-cores, 32 threads)

Intel® Core™ i9-13900K (3GHz P-Core base frequency, 2.2GHz E-Core base frequency, up to 4.3GHz E-Core Max Turbo frequency, up to 5.4 GHz P-core Max Turbo frequency, 36MB L3 cache, 8 P-cores and 16 E-cores, 32 threads)

Intel 12th Generation Processors:

Intel® Core™ i9-12900 (1.8GHz E-core base frequency, 5.0 GHz P-core base frequency, up to 3.8 GHz E-core Max Turbo frequency, up to 5.0 GHz P-core Max Turbo frequency, 30MB L3 cache, 8 P-cores and 8 E-cores, 24 threads)

Intel® Core™ i7-12700 (1.6 GHz E-core base frequency, 2.1 GHz P-core base frequency, up to 3.6 GHz E-core Max Turbo frequency. up to 4.8 GHz P-core Max Turbo frequency, 25MB L3 cache, 8 P-cores and 4 E-cores, 20 threads)

Intel® Core™ i5-12500 (3.0 GHz P-core base frequency, up to 4.6 GHz P-core Max Turbo frequency, 18MB L3 cache, 6 P-cores and 0-E-cores, 12 threads)

Intel® Core™ i3-12100 (3.3 GHz P-core base frequency, up to 4.3 GHz P-core Max Turbo frequency, 12MB, 4 P-cores. 8 threads)

- ¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
- ³ Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.



Overview

Intel vPro® requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro® Essentials and Enterprise vary. See http://intel.com/vpro

⁵ Memory will run at 4400 speed (MT/s) in 2DPC within 1DIMM population; memory will run at 4000 speed (MT/s) in 2DPC within 2DIMM of 1 Rank population and memory will run at 3600 speed (MT/s) in 2DPC within 2DIMM of 2 Rank population

Color Black Convertibility No

Expansion Slots (see

system board section for Slot 2: PCIe Gen3 x1 - with x4 open end Connector

more details)

Slot 3: PCIe Gen3 x4 - with x16 Connector

Slot 4: PCIe Gen3 x4 with open end connector

Expansion Bays (see storage section for more (1) External 5.25" bay

(2) Internal 3.5" bays

Slot 1: PCIe Gen5 x16

details)

(1) Internal 2.5" bay (for SSD only)

(1) Dedicated 9.5mm slim optical disk drive bay

Front I/O

(2) USB-A 10Gbps ports (1 charge port supports up to 5V/2.1A), (2) USB-A 10Gbps ports, (1) USB-C 20Gbps eport (charge supports up to 5V/3A, optional), (1) SD card reader (optional), (1) universal audio

jack

Internal I/O [5]

(1) Hi-Speed USB 480Mbps header for SD card reader

(1) serial port available with header (1) serial and PS/2 available with header

Rear I/O

(2) DisplayPort 1.4 ports, (1) Audio Line out, (1) Audio Line in, (1) 1GbE LAN, (3) Hi-Speed USB 480Mbps ports, (2) USB-A 10Gbps ports, (1) USB-A 5Gbps port, (1) serial (optional), (1) Flex I/O port (VGA, HDMI 2.0b, DisplayPort 1.4, USB-C® 10Gbps port (Power Delivery 15W, Alt Mode Display Port), (1) Dual USB-A 5Gbps port, (1) 2nd 1GbE LAN, (1) Thunderbolt 3 with USB4 USB-C® 40Gbps (cabled to PCIe AIC)*, (1)

1Gbps Fiber LC NIC

Optional I/O

Flex IO* - choose one of the following options: (1) DisplayPort™ 1.4 port, (1) HDMI 2.0b, (1) VGA,(1) 2nd 1GbE LAN. (1) 1Gbps Fiber LC NIC, (1) Dual USB-A 5Gbpsport, (1) USB -C® 10Gbps port (15W USB Power Delivery, Alt Mode DisplayPort™), (1) Thunderbolt™ 3 with USB4 USB-C® 40Gbps port (cabled to PCIe® AIC**);

Front – (1) USB-C[®] 20Gbps port (charging), (1) SD card reader;

Front – choose one of the following options: (1) USB-C @ 20Gbps (charging), (1) SD 4.0 card reader

Rear -(1) serial;

*About Thunderbolt compatibility, please refer to the FAQ of Thunderbolt community. https://www.thunderbolttechnology.net/tech/fag

**Flex IO port and PCIe slot 4 will be occupied when Thunderbolt is installed.

SD card reader (optional) **Interfaces Supported**

On-board RAID Support SATA and NVME RAID 0 Striped Array

SATA RAID and NVME RAID 1 Mirror Array



Overview

Chassis Dimensions (H x H: 14" [356mm]

W x D) W: 6.7" [169mm]

D: 15.2" [385mm]

H: 20.39" (518mm) **Packaged Dimensions**

W: 11.61" (295mm) D: 19.29" (490mm)

Rack Dimensions

Exact weights depend upon configuration (System weight only). Weight

Starting at 6.2kg (13.7lbs.)

Operating: 5° to 35° C (40° to 95° F) **Temperature**

Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for

every 305 m (1.000 feet) increase in elevation Non-operating: -40° to 60° C (-40° to 140° F)

Maximum rate of change: 10°C/hr

Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb **Humidity**

Non-operating: 10% to 90% RH, non-condensing, 35° C maximum wet bulb

Maximum Altitude (non- Operating (with Rotational Hard Drives): 3,048 m (10,000 feet) pressurized)6 Operating (with only Solid-State Drives): 5,000 m (16,404 feet)

Non-operating: 12,192 m (40,000 feet)

Maximum operating temperature is reduced as altitude increases. See

Temperature for details.

700W wide-ranging, active Power Factor Correction, 92% Efficiency with two 6+2 graphics power **Power Supply**

connectors. 500W wide-ranging, active Power Factor Correction, 90% Efficiency. 450W wide-ranging, active Power Factor Correction, 90% Efficiency, 350W wide-ranging, active Power Factor Correction,

92% Efficiency.

NOTE: The Power Supply Efficiency Report for the 700W 92% Efficiency, 500W 90% Efficiency, 450W

90% Efficiency and 350W 92% Efficiency Power Supply may be found at the following links:

https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2

500W PSU:

LiteOn 500W PSU Efficiency Report **Delta 500W PSU Efficiency Report**

450W PSU:

https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2

350W PSU:

AcBel 350W PSU (SFF) Efficiency Report AcBel 350W PSU (Custom) Efficiency Report

Delta 350W PSU Efficiency Report

For a complete listing of compatible DAT tape drives, LTO tape drives and RDX Removable Disk Backup **Backup Devices**

System offerings, please visit http://www.hp.com/go/connect

Intel® W680 chipset Chipset

Memory 4 DIMM slots, supporting up to 128GB ECC/non-ECC, DDR5 4800 MT/s speed depending on the system

configuration



Supported Components

SATA

A Hard Drives		Factory Configured	Option Kit	Option Kit Part Number
	500GB SATA 7200 rpm 6Gb/s 3.5" HDD	Υ	Υ	LQ036AA
	1TB SATA 7200 rpm 6Gb/s 3.5" HDD	Υ	Υ	LQ037AA
	2TB SATA 7200 rpm 6Gb/s 3.5" HDD	Υ	Υ	QB576AA
	1TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Υ	Υ	WOR10AA
	2TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Υ	Υ	2Z274AA
	4TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Υ	Υ	K4T76AA
	8TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Υ	Υ	2Z273AA
	12TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Υ	Υ	5S461AA
	500GB SATA 7.2K SED HDD	Υ	Υ	D8N29AA

NOTE: For internal bay install, HDD option kits require separate purchase of 6Z9U6AA HP Z2 Tower HDD Cable Kit. For external bay install, HDD options kits require separate purchase of 6Z9U6AA HP Z2 Tower HDD Cable Kit & NQ099AA HP Optical Bay HDD Mounting Bracket.

PCIe Solid State Drives

HP ZTurbo 512GB PCIe-Gen 4x4 TLC Z2 SSDKit	Υ	Υ	201G0AA/AT
HP ZTurbo 512GB PCIe-Gen 4x4 SED Z2 SSDKit	Υ	Υ	201F9AA
HP ZTurbo 1TB PCIe-Gen 4x4 TLC Z2 SSDKit	Υ	Υ	201F5AA/AT
HP ZTurbo 2TB PCIe-Gen 4x4 TLC Z2 SSDKit	Υ	Υ	201F8AA
Z Turbo 1TB 2280 PCIe-Gen4x4 Self Encrypted OPAL2 TLC M.2 Z2 SSD	Υ	Υ	223A3AA/AT
Z Turbo 2TB 2280 PCIe-Gen4x4 Self Encrypted OPAL2 TLC M.2 Z2 SSD	Υ	Υ	223A4AA/AT
256GB 2280 PCIe-4x4 NVMe Value M.2 Z2 Kit SSD	Υ	Υ	4M9Z1AA
512GB 2280 PCIe-4x4 NVMe Value M.2 Z2 Kit SSD	Υ	Υ	4M9Z2AA
1TB 2280 PCIe-4x4 NVMe Value M.2 Z2 Kit SSD	Υ	Υ	4M9Z3AA
Z Turbo 4TB 2280 PCIe-4x4 TLC M.2 Z2 Kit SSD	Υ	Υ	5S492AA
Z Turbo 2TB PCIe-4x4 TLC SSD Module	Υ	Υ	38T75AA
Z Turbo 1TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Υ	Υ	38T76AA
Z Turbo 1TB PCIe-4x4 TLC SSD Module	Υ	Υ	38T77AA
Z Turbo 2TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Υ	Υ	38T79AA
Z Turbo 512GB PCIe-4x4 TLC SSD Module	Υ	Υ	38T80AA
Z Turbo 512GB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Υ	Υ	38T81AA
Z Turbo 4TB 2280 PCIe-4x4 TLC M.2 SSD Module	Υ	Υ	5S496AA
Z Turbo 4TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Υ	Υ	5S497AA
Z Turbo 4TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z2 Kit SSD	Υ	Υ	5S498AA
NAME OF A STATE OF A S			

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Graphics Option Kit

Factory Part Supported Support Configured Option Kit Number # of cards Notes



Supported Components

Graphics Cable Adapters	HP DisplayPort To HDMI True 4k Adapter	Υ	Υ	2JA63AA		
diapilics cable Adapters	HP Single miniDP-to-DP Adapter Cable	Y	Y	2MYO5AA		
	HP DisplayPort To DVI-D Adapter	Y	Y	FH973AA		
	HP DisplayPort To DVI Adapter (Bulk 90)	Ϋ́	Y	FH973A6		
	The Displays of the Davindapter (Balk 50)	•	Y	AS615AA/		
	HP DisplayPort To VGA Adapter	Υ	•	AT		
	HP DisplayPort to VGA Adapter Bulk		Υ			
	Qty.90)	Υ		AS615A6		
	HP DisplayPort To VGA Adapter	Y	Y	F7W97AA		
	HP USB-C to DisplayPort Adapter	Y	Y	4SH08AA		
	HP USB-C to HDMI Adapter	Y	Y	4SH07AA		
	HP USB-C to VGA Adapter	Υ	Υ	4SH06AA		
Entry 3D	NVIDIA® T400 4 GB Graphics ²	Y	Υ	5Z7EOAA/ AT	2	1
	NVIDIA® T600 4 GB Graphics ¹	N	Υ	340K9AA	2	1
	AMD Radeon Pro WX 3200 4GB	Υ	Υ	6YT6*AA/ AT	1	1
	AMD Radeon RX 6400 4 GB DH DP+HDMI Graphics	N	Υ	6Q3U4AA/ AT	1	1
Mid-range 3D	NVIDIA® T1000 4 GB Graphics	Υ	Υ		2	1
	NVIDIA® T1000 8 GB Graphics	Υ	Υ	5Z7D8AA/ AT	2	1
	NVIDIA Long-Life T1000E 8 GB 4mDP Graphics	Υ	Υ	6V9V4AA/ AT	2	1
	NVIDIA RTX™ A2000 6 GB 4mDP Graphics*	Υ	Υ	340L0AA	2	
	NVIDIA RTX™ A2000 12GB Graphics*	Υ	Υ	5Z7D9AA/ AT	2	
	NVIDIA RTX 2000 Ada 16 GB 4mDP Graphics	Υ	Υ	8D6B8AA	2	
	NVIDIA RTX™ A4000 16GB*	Υ		20X24AA/ AT	2	
	NVIDIA Long-Life RTX A4000E 16 GB 4DP Graphics*	Υ	Υ	6H7J7AA	1	
	NVIDIA RTX™ 4000 Ada 20 GB 4DP Graphics*	Υ	Υ	8D6B7AA	2	
	NVIDIA Long-Life RTX A2000E 12 GB 4mDP Graphics	Υ	Υ	6V9V5AA/ AT	2	
	AMD Radeon™ Pro W6600 Graphics (8GB GDDR6 dedicated) *	Υ	Υ	340K5AA	1	
High-End 3D	AMD Radeon™ Pro W6800 Graphics (32 GB GDDR6 dedicated) *	Υ	Υ	340K7AA	1	
	AMD Radeon Pro W7900 48 GB 3DP+1mDP Graphics	Υ	Υ	8F699AA	1	
	AMD Radeon Pro W7600 8 GB Graphics*	Υ		8D6B9AA	1	
	AMD Radeon Pro W7500 8 GB Graphics	Υ	Υ	8D6C2AA	1	
	NVIDIA RTX 4500 Ada 24 GB 4DP Graphics	Y	Υ	8D6C1AA	1	



Supported Components

NVIDIA® RTX™ A5000 24 GB Graphics*	Υ	Y	20X23AA/ AT	1
NVIDIA RTX 5000 Ada 32 GB 4DP Graphics	Υ	Υ	8D6B6AA	1
AMD Radeon™ RX 6700 XT 12GB*	γ	Υ	4C2O3AA	1

NOTE: Z2 G9 Tower with 700W PSU can support up to a 250W professional graphics card from HP, either factory-configured or added via after-market option, and can support up to 320W total graphics power when graphics is factory-configured.

Note 1: When dual graphics is configured the 450W and 500W base units will require the AMO HP Z2 TWR Dual Front Fan Kit part number 4N007AA; One storage device configuration for higher than 75W graphics cards (T1000 and up)

^{*} Requires 700W chassis.

Memory		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP 8GB (1x8GB) DDR5-4800 nECC UDIMM	Υ	Υ	4M9X9AA	
	HP 16GB (1x16GB) DDR5-4800 nECC UDIMM	Υ	Υ	4M9Y0AA	
	HP 16GB (1x16GB) DDR5-4800 ECC UDIMM	Υ	Υ	4M9Y1AA	1
	HP 32GB (1x32GB) DDR5-4800 nECC UDIMM	Υ	Υ	4M9Y2AA	
	HP 32GB (1x32GB) DDR5-4800 ECC UDIMM	Υ	Υ	4M9Y3AA	1

NOTE 1: ECC memory is supported

GENERAL NOTE: Two channels of DDR5 memory are supported. To realize full performance at least one DIMM must be inserted into each channel.

Though the memory modules can run up to 4800MHz, the current platform will support maximum memory speed of 4400MHz.

The system speed will be determined by a number of key factors:

Module Configuration	Description of configuration	Max Memory Speed (Actual Memory speed is dependent on CPU)
Single DIMM per channel	Configurations that contain only one or two DIMM modules with DIMMs only in the black slots	4400MHz
Two single ranked DIMMs in a channel	Configurations with 3 or 4 single ranked DIMMs (8GB and 16GB) installed in a system	4000MHz
Two dual ranked DIMMs in a channel	Configurations with 3 or 4 dual ranked DIMMs (32GB) installed in a system	3600MHz

When more than one memory slot is populated, symmetric configurations are required for 2 DIMMs per channel. Mix of different part numbers or mix of single and dual ranks within a channel is not allowed.

Optical and Removable Storage		Factory Configured	Option Kit	Option Kit Part Number
	HP DX175 Removable HDD Frame/Carrier	N	Υ	1ZX71AA
	HP DX175 Removable HDD Spare Carrier	N	Υ	1ZX72AA
	HP Z2 TWR SuperMulti DVD-Writer 9.5mm Slim ODD	Υ	Υ	4L5K0AA



Supported Components

HP Z2 TWR DVD-ROM 9.5mm Slim ODD	Υ	Υ	4L5K1AA
HP CRU QX328 5.25 in Front Removable M.2 Frame/Carrier	Υ	Υ	4N011AA
HP CRU Secure High Performance Storage Module with 2TB M.2 SSD	Υ	Υ	56Q87AA
HP CRU Secure High Performance Storage Module with 1TB M.2 SSD	Υ	Υ	56Q88AA
HP CRU Secure High Performance Storage Module with 512GB M.2 SSD	Υ	Υ	56Q89AA
HP CRU SHIPS M.2 Spare Carrier	Υ	Υ	633X9AA

NOTES: Duplication of copyrighted material is strictly prohibited. Actual speeds may vary. Double Layer media compatibility will widely vary with some home DVD players and DVD-ROM drives. Note that DVD-RAM cannot read or write to 2.6GB Single Sided/5.2 Double Sided-Version 1.0 Media.

4N011AA HP CRU QX328 5.25in Front Removeable Frame/Carrier requires a separate purchase of HP CRU SHIPS Storage Module(s).

HP CRU Secure High Performance Storage (SHIPS) Module Kit contains select M.2 SSD for install into a factory configured or after market option front removeable storage carrier (HP CRU QX328 Frame/Carrier).

Networking and Communications		Factory Configured	Option Kit	Option Kit Part Number
	Integrated Intel® I219LM PCIe GbE Controller (Intel® vPro® with Intel® AMT 16.0)	Υ	N	
	HP 1GbE LAN Flex Port 2020	Υ	Υ	141J6AA/AT
	HP Flex 1GbE Fiber LC Single Port	Υ	Υ	20J15AA
	NVIDIA Mellanox ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC ¹	Y	Υ	436M8AA
	HP 10GbE SFP+ SR/SW LC Fiber Optic Transceiver	Υ	Υ	860T8AA
	HP 25GbE SFP28 LC Fiber Optic Transceiver	Υ	Υ	860T9AA
	Intel Ethernet I350-T4 4-Port 1Gb NIC*	N	Υ	W8X25AA
	Intel X550 10GBASE-T Dual Port NIC	Υ	Υ	1QL46AA
	Intel Ethernet Network Adapter I225-T1	Υ	Υ	406L9AA
	Intel Wi-Fi 6E AX211 BT 5.3 wireless card M.2 non-vPro ^{1,**,***}	Υ	N	
	Allied Telesis AT-2911T/2-901 Dual Port 1GbE NIC	Υ	Υ	6E3Y9AA/AT

Intel BE200 Wi-Fi 7 +Bluetooth 5.4 non-vPro WW WLAN****

*Intel I350-T4 4-port GbE NIC is an After Market Option only.

Υ

NOTES:

The integrated network connection is required to support Intel® vPro® Technology.



¹ Intel AX211 with Internal antenna support WIFI 6/WIFI 6E

^{**}Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.

^{***}Intel AX211 must be configured at time of purchase. Not available as an After Market Option.

^{****} Not available with 12th Gen Intel ADL processors; Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 7 (802.11BE) functionality requires Windows 11 24H2, select Intel® processor, and a Wi-Fi 7 router, sold separately. Wi-Fi 7 is backwards compatible with prior 802.11 specs. Available in countries where Wi-Fi 7 is supported.

Supported Components

If AMT is provisioned, then network teaming with the integrated LAN port is not possible.

"Gigabit" Ethernet indicates compliance with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/sec. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.



Supported Components

Supported Compo	nencs			
Input Devices		Factory Configured	Option Kit	Option Kit Part Number
	HP USB 320K Keyboard	Y	Υ	9SR37AA
	HP 320M Wired Mouse	Υ	Υ	9VA80AA
	HP Wired Desktop 320MK Mouse and Keyboard	N	Υ	9SR36AA
	HP 125 Wired Keyboard	Υ	Υ	266C9AA
	HP 975 USB+BT Dual Mode Wireless	N	Υ	3Z726AA
	HP 655 Wireless USB BLK KBD/MSE Kit	N	Υ	N/A
	HP 125 Wired Mouse	Υ	Υ	265A9AA
	HP 128 Laser Wired Mouse	Υ	Υ	265D9AA
	HP 935 Creator Wireless Mouse	N	Υ	1DOK8AA
	HP 455 Programmable Wireless Keyboard	Υ	Υ	4R177AA
	HP 455 Programmable Wireless Keyboard (Bulk Qty.12)	Υ	Υ	4R177A6
	HP 655 Wireless Keyboard and Mouse Combo	Υ	Υ	4R009AA
	HP 655 Wireless Keyboard and Mouse Combo (Blk Qty.10)	Υ	Υ	4R009A6
	NOTE: Keyboard and Mouse are optional or add on features.			
Flex Module (Rear IO)		Factory Configured	Option Kit	Option Kit Part Number
	HP 1GbE LAN Flex Port 2020	Υ	Υ	141J6AA/AT
	HP DP Flex Port 2020	Υ	Υ	141J7AA/AT
	HP Dual USB-A 3.2 Gen1 Flex Port 2020	Υ	Υ	141J8AA/AT
	HP HDMI Flex Port	Υ	Υ	69D47AA/AT
	HP USB-C 3.2 Gen2 Alt Flex Port 2020	Υ	Υ	141K6AA/AT
	HP VGA Flex Port 2020	Υ	Υ	141K7AA/AT
	HP Flex 1GbE Fiber LC Single Port	Υ	Υ	20J15AA
Other Hardware		Factory Configured	Option Kit	Option Kit Part Number
	HP Single TBT3 wType C and USB4 PCIe x4 Card	Υ	N	N/A
	HP Z2 Internal Serial Port and PS/2 Port	Υ	Υ	141K9AA/AT
	HP Z2 Power Cord Kit	Υ	Υ	1N1D5AA
	C13-C14 2.0m 15A 100-127V Countries Straight Desktop Power Cord	Υ	Υ	8R881AA
	C13-C14 2.0m 10A 200-240V Countries Straight Desktop Power Cord	Y	Υ	8R882AA
	HP Z2 2 nd serial port adapter	Υ	Υ	141K8AA/AT
	HP Z2 Tower Dust Filter	Υ	Υ	141L2AA/AT
	HP Z2 Tower Dust Filter and bezel	Υ	Υ	141L3AA/AT
	HP PCIe x1 Parallel Port Card	Υ	Υ	N1M40AA



Υ

Υ

Υ

Ν

Υ

Υ

Υ

Υ

Υ

HP Z2 G9 Single Type-C SuperSpeed USB 20Gbps Front Port

HP Z2 TWR Dual Front Fan Kit

HP Z2 Tower HDD Cable Kit

HP Optical Bay HDD Mounting Bracket

HP Integrated Remote System Controller

4M9X8AA/AT

4N007AA

NQ099AA

6Z9U6AA

7K6D9AA

QuickSpecs

Supported Components

HP Remote System Controller Main Board Adapter	Υ	Υ	7K6D8AA
HP Remote System Controller	Υ	Υ	7K6D7AA
HP Remote System Controller for Universal KVM	N	Υ	7K7N2AA

Racking and Physical Security		Factory Configured	Option Kit	Option Kit Part Number
	HP Z2 Mini and Z2/Z4/Z6 TWR Depth Adjustable Fixed Rail Rack Kit	Υ	Y	2A8Y5AA
	HP Keyed Cable Lock	Υ	Υ	T1A62AA
	HP Master Keyed Cable Lock 10mm	Υ	Υ	T1A63AA
	HP Business PC Security Lock V3 Kit	Υ	Υ	3XJ17AA

Software		Factory Configured	Option Kit	Support Notes
	HP Performance Advisor	Υ	N	1
	HP PC Hardware Diagnostics UEFI (Windows OS only)	Υ	N	2
	HP PC Hardware Diagnostics Windows		N	3
	HP Wolf Security	Υ	N	
	HP Notifications	Υ	N	
	HP Desktop Support Utility	Υ	N	
	HP Documentation	Υ	N	
	HP Image Assistant	N	N	
	HP Support Assistant	N	N	
	myHP	Υ	N	
	HP Easy Clean	Υ	N	
	Kingsoft WPS Office	Υ	N	4
	My Office	Υ	N	5
	Adobe Substance 3D Collection Plan	N	Υ	6
	WSL2/Ubuntu Data Science Stack	Υ	N	7

Notes:

- Supports, and preinstalled with Windows 10 only. Also available as a free download from 1. http://www.hp.com/go/performanceadvisor
- 2. Windows OS only
- 3. Not available in Russia
- 4. Only available in China
- Only available in Russia
- Not available in China
- 7. Optional Software

Operating Systems

Windows 11 Pro - HP recommends Windows 11 Pro²

Windows 11 Home - HP recommends Windows 11 Pro²

Windows 10 Pro (available through downgrade rights from Windows 11 Pro) 1,2,3

Linux®-ready⁵

Ubuntu®4,5



Supported Components

- Intel 12th generation processors will support and preinstall Ubuntu 20.02 and 20.04.
- o Intel 13th generation processors support and preinstall Ubuntu 22.04 LTS

¹ Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

² Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

³This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

⁴ Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply and additional requirements may apply over time for updates.

⁵For detailed Linux® OS/hardware support information, see: http://www.hp.com/support/linux_hardware_matrix

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282



Supported Components

HP BIOS

Additional HP BIOS Features:

- Power-On password Helps prevent an unauthorized user from powering on the system.
- Administrator password Also known as the BIOS Setup password, this helps prevent unauthorized changes to the system configuration. If the administrator password is not known, the BIOS cannot be updated and changes cannot be made to BIOS settings using BIOS Setup or under the OS.
- S4/S5 Maximum Power Savings setting supports EU Lot6 requirement and allows the computer to power down below 0.5W in S4/S5 (when turned off). When S4/S5 Maximum Power Savings feature is enabled below features are turned off:
 - -Power to expansion connectors / slots
 - -Most Wake events other than power buttons and WOL(Wake on LAN supported by embedded Lan controller under S4/S5 Maximum Power Saving Enabled)
 - -USB charging ports

HP Sure Start Gen7 Start

- BIOS Integrity checking Sure Start protection ensures that only trusted BIOS code is executed and not rootkits, viruses and malware. Verification is done upon boot up, shutdown and while the system is on.
- Sure Start is set by default to automatically repair the BIOS if corrupted or compromised but is policy driven for better manageability. Start is set by default to automatically repair the BIOS if corrupted or compromised but is policy driven for better manageability.
- Protecting beyond BIOS Integrity checking and repair is extended to other data that should be protected such as network configuration parameters, platform specific information (i.e. system IDs), secure boot credentials, and other code the system needs to boot.
- Audit enabled System Audit via Sure Start Event Logs capture data such as incident, repair date and time for troubleshooting and investigating

NOTE: HP Sure Start Gen7 is available on HP Workstation products equipped with Intel® 12th generation processors.

HP Performance Control Modes

HP Z Desktop Workstations offers Performance Control Modes in the F10 BIOS menu. Z2 G9 offers Quiet Mode, Performance Mode and High-Performance Mode. HP recommends using High Performance Mode unless you have concerns about acoustics in an open office environment. Customers can get up to 34% performance improvements using High Performance Mode over Performance Mode*. It is possible to configure High Performance Mode as default from the factory.

How to Set HP Performance Control Modes in HP F10 BIOS Menu

In the F10 BIOS Menu, the setting titled "Performance Control" is adjustable to High Performance Mode, Performance Mode or Quiet Mode. These modes are choice points for performance and acoustic tradeoffs based on user needs or recommended balanced conditions in performance and noise optimization.

At startup, push the F10 key while system is booting to get to the BIOS Menu.
Go to → Advanced -> System Options ->scroll down and choose "Performance Control"

Set the Performance Mode you desire and then go back to Main->Save Changes and Exit -> Yes The machine will restart in the mode you've chosen.

How to set HP Performance Mode in HP Performance Advisor software, select BIOS Settings -> Advanced -> System Options -> Performance Controls

The machine will restart in the mode you've chosen.



Supported Components

You can change these modes anytime you prefer to prioritize acoustics (Quiet Mode), want a balance between performance and acoustics (Performance Mode) or prefer to prioritize performance (High Performance Mode).

For more information on performance control modes, please see the white paper called, HP Performance Control Modes for Z Desktop Workstations.

*Compared to Performance Mode. Performance increase based on Z2 Tower G9 with 64GB of memory, 1TB NVMe, Windows 11 22H2 OS, RTX A4000, i9-13900 CPU using SPECworkstation 3.1

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Software

HP Support Assistant 14

HP Image Assistant

HP Desktop Support Utility

HP Documentation

HP Notifications

HP PC Hardware Diagnostics UEFI

HP PC Hardware Diagnostics Windows

HP Performance Advisor¹

myHP

HP Easy Clean²⁰

WSL/Ubuntu Data Science Stack

HP Privacy Settings

Touchpoint Customizer for Commercial

Manageability Features

HP Driver Packs²

HP UWP Pack

HP System Software Manager (SSM)

HP Manageability Integration Kit Gen43

HP Smart Support⁵

HP Client Catalog (download)

HP Image Assistant (download)

HP Cloud Recovery

HP Client Management Script Library (download)

HP BIOSphere Gen6 13

Client Security Software

HP Client Security Suite Gen74 including: (including Credential Manager, HP Password Manager6, HP Spare Key)

HP Power On Authentication

Microsoft Defender⁷

Security Management

HP Secure Erase 16

HP Wolf Pro Security Edition (optional) 18

HP Wolf Security for Business²² Includes:

HP Sure Click¹¹

HP Sure Sense¹²

HP Sure Run Gen59

HP Sure Recover Gen4 10



Supported Components

HP Sure Start Gen78

HP Tamper Lock

HP Sure Admin 17

HP Client Security Manager Gen 74

- ¹ HP Performance Advisor Software -P Performance Advisor is ready to help you get the most out of your HP Workstation from day one—and every day after. Learn more or download at: http://hp.com/PerformanceAdvisor
- ² HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- ³ HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html
- ⁴ HP Client Security Manager Gen7 requires Windows and is available on the select HP PCs.
- ⁵ HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights and is available preinstalled on select products, thru HP Factory Configuration Services; or it can be downloaded. For more information about how to enable HP Smart Support or for download, please visit http://www.hp.com/smart-support.
- ⁶ HP Password Manager requires Internet Explorer or Chrome or FireFox. Some websites and applications may not be supported. User may need to enable or allow the add-on / extension in the internet browser.
- ⁷ Microsoft Defender Opt in and internet connection required for updates.
- ⁸ HP Sure Start Gen 7 is available on select HP PCs and workstations. See product specifications for availability.
- ⁹ HP Sure Run Gen5 is available on select Windows 11 based HP Pro, Elite and Workstation PCs with select Intel® or AMD processors
- ¹⁰ HP Sure Recover Gen4 is available on select HP PCs and requires Windows 10 and an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module
- 11 HP Sure Click requires Windows 10 Pro or higher or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details.
- ¹² HP Sure Sense requires Windows 11 Pro or Enterprise and supports Microsoft Internet Explorer, Google Chrome™, and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.
- 13 HP BIOSphere Gen6 features may vary depending on the platform and configurations.
- ¹⁴ HP Support Assistant requires Windows and Internet access.
- ¹⁶ Secure Erase –or the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "C"ear" "anitation method. HP Secure Erase does not support platforms with Intel® Optane.
- ¹⁷ HP Sure Admin requires Windows 11, HP BIOS, HP Manageability Integration Kit from
- http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.
- ¹⁸ HP Wolf Pro Security Edition is available preloaded on select SKUs and, depending on the HP product purchased, includes a paid 1-year or 3-year license. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software -nd-User license Agreement (EULA) that can be found at: https://support.hp.com/us-
- en/document/ish_3875769-3873014-16 as that EULA is modified by the following: "7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition (HP Sure Sense Pro and HP Sure Click Pro) is effective upon activation and will continue for either a twelve (12) month or thirty-six (36) month license term ("Initial Term"). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support.
- ²⁰ HP Easy Clean requires Windows 10 RS3 and higher and will disable the keyboard, touchscreen, and clickpad only. Ports are not disabled. See user guide for cleaning instructions.
- ²² HP Wolf Security for Business requires Windows 10 or higher, includes various HP security features and is available on HP Pro, Elite, RPOS and Workstation products. See product details for included security features



System Technical Specifications

System Board

System Board Form

Factor Customized PCB 36.056 x 25.130 mm (14.197 x 9.894 inch)

Processor Socket Single LGA-1700

CPU Bus Speed DMI Gen4

Chipset Intel® PCH W680 Super I/O Controller Nuvoton SIO21

Memory Expansion Slots 4 DDR5 memory slots

Memory Type Supported DDR5, UDIMM (Unbuffered), ECC& non-ECC

Memory Modes Non-Interleaved for single channel. Interleaved when both channels are populated.

Memory Speed Supported 3600MT/s to 4400MT/s DDR5, dependent on memory configuration1

¹Though the memory modules can run up to 4800MHz, the current platform will only be able to support the maximum memory speed of 4400MHz.

The system speed will be determined by a number of key factors:

Description of configuration Module **Max Memory Speed (Actual Memory** Configuration speed is dependent on CPU)

Single DIMM per channel

Configurations that contain only one or two DIMM modules with DIMMs only in the black slots 4400MHz

Two single ranked DIMMs in a channel Configurations with 3 or 4 single ranked DIMMs (8GB and 16GB) installed in a system

4000MHz

Two dual ranked

Configurations with 3 or 4 dual ranked DIMMs

3600MHz

DIMMs in a channel

(32GB) installed in a system

Memory Protection ECC available on data

Maximum Memory 128GB

Memory Configuration

(Supported)

8GB, 16GB and 32GB non-ECC, 16GB and 32GB ECC unbuffered DIMMs are supported. ECC and non-ECC memory DIMMs cannot be mixed in the same system

PCI Express Connectors

- (1) PCI Express Gen5 slot x16 mechanical/x16 electrical (full height, full length)
- (1) PCI Express Gen3 slot x4 mechanical/ x1 electrical (full height, full length, open-ended)
- (1) PCI Express Gen3 slot x16 mechanical/ x4 electrical (full height, full length)
- (1) PCI Express Gen3 slot x4 mechanical/ x4 electrical (full height, full length, open-ended)
- (1) M.2 2280 Storage (PCIe Gen4 x4) (1) M.2 2280 Storage (PCIe Gen4 x4)
- (1) M.2 2280 Storage (PCIe Gen4 x4)
- (1) M.2 2230 WLAN (PCIe Gen3 x1+ Intel CNVi)

NOTE: The PCIe Gen5 x16 slot has validated and passed PCI-SIG electrical compliance test ONLY. HP does not quarantee and support any PCIe Gen5 cards available -in the open market. May or may not see performance reduced when device MRRS (Maximum Read Request Size) is 512Bytes and above. To reach highest Gen5 PCIe performance, Use the top bin DRAM module (e.g. 4400) to minimize the impact.

Supported Interfaces

SATA Integrated (4) Serial ATA interfaces (6Gb/s SATA).

RAID 0 and 1 supported. Factory integrated RAID for

Microsoft Windows only.

Intel® UHD Graphics 730 (on Core i5-12400/i3-12300/i3-**Integrated Graphics**

12100) processors); Intel® UHD Graphics 770 (on 13th and

14th gen Core i5/i7/i9 processors):



System Technical Specifications

Based on Unified Memory Architecture (UMA) - – region of system memory is reserved and dedicated to the graphics display.

Support for Microsoft DirectX 12, OpenGL 4.6 and OpenCL 3.0

on Intel® UHD Graphics 730/770;

Based on Unified Memory Architecture (UMA) - - region of system memory is reserved and dedicated to the graphics

display.

2 DP 1.4 graphics ports integrated in motherboard; Supports

up to three simultaneous displays across

DisplayPort*/HDMI*/DVI outputs.

Max. resolution supported on onboard DP 1.4/HBR2 ports:

4096x2304 @ 60Hz, 24bpp

Max. resolution supported on FlexIO DP 1.4/HBR3 port:

5120x3200 @60Hz, 24bpp

Network Controller Integrated Ethernet PHY Connection I219LM. Management

capabilities: WOL, PXE 2.1 and AMT 16

Serial 1 internal header (requires optional Serial Port and PS/2

Combo Kit with PCIe bracket)

2^{nd S}erial 1 internal header(requires optional Serial Port Adapter Kit)

USB Connector(s) Front 2 Type-A SuperSpeed USB 10Gbps signaling rate port (charge

supports up to 5V/2.1A);

2 Type-A SuperSpeed USB 10Gbps signaling rate port; 1 Type-C[®] SuperSpeed USB 20Gbps signaling rate port

(optional, charge supports up to 5V/3A)

Rear 3 High-speed USB 480Mbps signaling rate port; 1 Type-A

SuperSpeed USB 5Gbps signaling rate port; 2 Type-A

SuperSpeed USB 10Gbps signaling rate port;

Flex I/O option:

1 SuperSpeed USB Type-C[®] 10Gbps signaling rate (Power Delivery 15W, Alt Mode DisplayPort); 1 Dual SuperSpeed USB

Type-A 5Gbps signaling rate

Internal 1 High-speed USB 480Mbps signaling rate header for SD Card

Reader

HD Integrated Audio Realtek ALC3205

Flash ROM Yes
CPU Fan Header Yes
Memory Fan Header None

Chassis Fan Header 1 Rear System Chassis Fan Header, 1 Graphic chassis Fan Header.

Front PCI Fan Header None

Front Control

Panel/Speaker Header Yes

CMOS Battery Holder - -

ithium Yes

Integrated Trusted Integrated TPM 2.0 (Infineon SLB9672)

Platform Module Convertible to FIPS 140-2 Certified mode through firmware v15.21

Power Supply Headers Yes
Power Switch, Power LED
& Hard Drive LED Header Yes
Clear Password Jumper None



System Technical Specifications

Keyboard/Mouse USB or PS/2 (option)

Power Supply 700W EPA92, 500W EPA90, 450W EPA90 and 350W EPA92

¹Maximum memory capacities assume 64-bit operating systems, such as Genuine Windows® 10 Professional 64 bit, Red Hat Linux 64-bit. 32-bit Windows Operating Systems support up to 4 GB.

PROCESSORS

Name	Ghz P- Core Base Frequenc y	Ghz E- Core Base Frequenc y	Core Max	Up to x GHz E-Core Max Turbo Frequency	L3 Cache (MB)	P- Core S	E- Core s	Total Cores	Processo r Threads	Memory Speed (MT/s) (DDR5) ⁴	ECC Memory Supporte d ⁵	Integrated Graphics	Featuring Intel® vPro® Technolog y³	TDP (W)	Max Turbo Frequen cy (GHz)
Intel 14 th Gene	eration Pr	ocessors													
Intel® Core™ i9-14900K	3.2	2.40	5.6	4.4	36	8	16	24	32	5600	Y	Intel® UHD Graphics 770	Y	125	6
Intel® Core™ i9-14900	2	1.50	5.4	4.3	36	8	16	24	32	5600	Y	Intel® UHD Graphics 770	Y	65	5.8
Intel® Core™ i7-14700K	3.4	2.50	5.5	4.3	33	8	12	20	28	5600	Y	Intel® UHD Graphics 770	Y	125	5.6
Intel® Core™ i7-14700	2.1	1.50	5.3	4.2	33	8	12	20	28	5600	Y	Intel® UHD Graphics 770	Y	65	5.4
Intel® Core™ i5-14600K	3.5	2.60	5.3	4.2	24	6	8	14	20	5600	Y	Intel® UHD Graphics 770	Y	65	5.3
Intel® Core™ i5-14600	2.7	2.00	5.2	3.9	24	6	8	14	20	5600	Y	Intel® UHD Graphics 770	Y	65	5.2
Intel® Core™ i5-14500	2.6	1.80	5	3.7	24	6	8	14	20	4800	Y	Intel® UHD Graphics 770	Y	65	5.0
Intel® Core™ i5-14400	2.5	1.80	4.7	3.5	20	6	4	20	16	4800	N	Intel® UHD Graphics 730	N/A	65	4.7
Intel 13 th Gene	eration Pr	ocessors													
Intel® Core™ i9-13900K	3	2.20	5.4	4.3	36	8	16	24	32	5600	Y	Intel® UHD Graphics 770	Y	125	5.8
Intel® Core™ i9-13900	2	1.50	5.2	4.2	36	8	16	24	32	5600	Y	Intel® UHD Graphics 770	Y	65	5.6
Intel® Core™ i7-13700K	3.4	2.50	5.3	4.2	30	8	8	16	24	5600	Y	Intel® UHD Graphics 770	Y	125	5.8
Intel® Core™ i7-13700	2.1	1.50	5.1	4.10	30	8	8	16	24	5600	Y	Intel® UHD Graphics 770	Y	65	5.2
Intel® Core™ i5-13600K	3.5	2.60	5.1	3.9	24	6	8	14	20	5600	Y	Intel® UHD Graphics 770	Y	65	5.1
Intel® Core™ i5-13600	2.7	2.00	5.0	3.7	24	6	8	14	20	4800	Y	Intel® UHD Graphics 770	Y	65	5.0
Intel® Core™ i5-13500	2.5	1.80	4.8	3.5	24	6	8	14	20	4800	Y	Intel® UHD Graphics 770	Y	65	4.8
Intel® Core™ i5-13400	2.5	1.80	4.6	3.3	20	6	4	10	16	4800	N	Intel® UHD Graphics 730	N/A	65	4.6
Intel 12 th Gene	eration Pr	ocessors													
Intel® Core™ i9-12900	5	1.8	5.0	3.8	30	8	8	16	24	4800	Y	Intel® UHD Graphics 770	Y	65	5.1



²M.2 storage supports compatible devices up to 80mm

System Technical Specifications

Intel® Core™ i7-12700	2.1	1.6	4.8	3.6	25	8	4	12	20	4800	Υ	Intel® UHD Graphics 770	Υ	65	4.9
Intel® Core™ i5-12600	3.3	N/A	4.8	N/A	18	6	0	6	12	4800	Υ	Intel® UHD Graphics 770	Υ	65	4.8
Intel® Core™ i3-12100	3.3	N/A	4.3	N/A	12	4	0	4	8	4800	N	Intel® UHD Graphics 730	N/A	60	4.3

¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

Intel vPro® requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3^{rd p}arty software in order to run. Features of vPro® Essentials and Enterprise vary. See http://intel.com/vpro

⁵ Memory will run at 4400 speed (MT/s) in 2DPC within 1DIMM population; memory will run at 4000 speed (MT/s) in 2DPC within 2DIMM of 1 Rank population and memory will run at 3600 speed (MT/s) in 2DPC within 2DIMM of 2 Rank population



System Technical Specifications

System Configuratio	1						
Example Configuration	Processor Info	Core i5-1250	0,6C 3.0G 65W				
#1	Memory Info	2 x 8G DDR5	1800 UDIMM NI	ECC			
	Graphics Info	NVIDIA T400	4GB				
	Disks/Optical/Floppy	512GB SSD Z	Turbo				
	PSU	350W					
	Other	NA					
Energy Consumption		115	VAC	230	230 VAC		VAC
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows long Idle (S0)	17.	17.866		912	17.	804
	Windows short Idle (S0)	18.	926	19.	024	18.	883
	Windows Busy Typ (S0)	160	.167	155	.973	161	.10
	Windows Busy Max (S0)	192	.557	187	.067	193	.063
	Sleep (S3)	1.367	1.259	1.401	1.367	1.259	1.401
	Off (S5)	0.555	0.552	0.561	0.555	0.552	0.561
	Zero Power Mode (EuP)	0.	171	0.1	73	0.1	68
		•		•			
Heat Dissipation		115 VAC		230 VAC		100 VAC	
(Btu/hr)		LAN	LAN	LAN	LAN	LAN	LAN
		Enabled	Disabled	Enabled	Disabled	Enabled	Disabled
	Windows Idle (S0)	-	959	1	116		747
	Windows short Idle (S0)	1	576	<u> </u>	.91	1	429
	Windows Busy Typ (S0)	546.489		1	.181	1	.707
	Windows Busy Max (S0)	1	.003	1	.271	1	.732
	Sleep (S3)	4.664	4.296	4.78	4.664	4.296	4.78
	Off (S5)	1.894	1.883	1.914	1.894	1.883	1.914
	Zero Power Mode (EuP)		583	<u> </u>	59	0.5	573
Example Configuration	Processor Info	Core i7-1270	0,12C 2.1G 65V	N			
#2	Memory Info	2 x 16G DDR5	4800 UDIMM I	NECC			
	Graphics Info	NVIDIA T1000) 8GB				
	Disks/Optical/Floppy	512GB SSD Z	Turbo				
	PSU	450W					
	Other	NA		1		1	
Energy Consumption			VAC	1	VAC	1	VAC
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows long Idle (S0)	20.	169	20.	335	20.	087
	Windows short Idle (S0)	21.	222	21.	547	21.	195
	Windows Busy Typ (S0)	119	9.48	117	.953	120	.406
1	Windows Busy Max (S0)		7.13	-	5.03	1	.833
1	Sleep (S3)	1.575	1.461	1.582	1.575	1.461	1.582
	Off (S5)	0.944	0.941	0.952	0.944	0.941	0.952
	Zero Power Mode (EuP)	0.7	204	0.2	207	0.2	202
·	*						



System Technical Specifications

Heat Dissipation		115	VAC	230	VAC	100	VAC			
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled			
	Windows Idle (S0)	68.	817	69.383		68.537				
	Windows short Idle (S0)	72.	409	73.518		72.317				
	Windows Busy Typ (S0)	407	.666	402.457		410.824				
	Windows Busy Max (S0)	536.128		528.962		538	.527			
	Sleep (S3)	5.374	4.985	5.398	5.374	4.985	5.398			
	Off (S5)	3.221	3.211	3.248	3.221	3.211	3.248			
	Zero Power Mode (EuP)	0.6	96	0.7	'06	0.6	89			
Example Configuration #3	Processor Info	Core i9-12900,16C 2.4G 65W								
	Memory Info	2 x 16G DDR5	4800 UDIMM I	ECC						
	Graphics Info	NVIDIA RTX A	2000							
	Disks/Optical/Floppy	512GB SSD Z	Turbo							
	PSU	450W								
	Other	NA								
Energy Consumption		115	VAC	230	VAC	100 VAC				
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled			
	Windows long Idle (S0)	22.	555	23.	324	22.	484			
	Windows short Idle (S0)	23.	414	24.	656	23.	397			
	Windows Busy Typ (S0)	159	.883	156	.853	161	.463			
	Windows Busy Max (S0)	189	9.99	185	5.89	190.127				
	Sleep (S3)	1.585	1.492	1.694	1.585	1.492	1.694			
	Off (S5)	0.952	0.95	1.083	0.952	0.95	1.083			
	Zero Power Mode (EuP)	0.	21	0.217		0.198				

Heat Dissipation		115	115 VAC		230 VAC		VAC	
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	76.	958	79.581		76.715		
	Windows short Idle (S0)	79.889		84.126		79.831		
	Windows Busy Typ (S0)	545.522		535.184		550.913		
	Windows Busy Max (S0)	648	648.246		634.257		648.712	
	Sleep (S3)	5.408	5.091	5.78	5.408	5.091	5.78	
	Off (S5)	3.248	3.241	3.695	3.248	3.241	3.695	
	Zero Power Mode (EuP)	0.7	17	0.74		0.676		

NOTE: The Power Supply Efficiency report may be found at the following links:

https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2



System Technical Specifications

Operating Voltage Range 90-269 VAC **Rated Voltage Range** 100-240 VAC **Rated Line Frequency** 50-60 Hz **Operating Line Frequency** 47-63 Hz

Range

Rated Input Current 8.2A @ 100-240V

Heat Dissipation Typical: 1598.101 btu/hr (402.984 kcal/hr)

Yes

Maximum: 1619.608 btu/hr (408.407 kcal/hr)

Yes, with Wake-on-LAN disabled: <1W in S4/S5 - -ower Off

ENERGY STAR® certified

(Config Dependent)

CECP Compliant @ 220V Yes

FEMP Standby Power

Compliant

Built-in Self Test (BIST)

LED

Surge Tolerant Full Yes **Ranging Power Supply** (withstands power surges

up to 2000V)

Hood Lock Header Yes ErP Lot 6- Tier 1 Yes Compliance @ 230V (<1W

in S5 - -ower Off)

ErP Lot 6- Tier 2 Yes

Compliance @ 230V (<0.5W in S5 - -ower Off)

Declared Noise Emissions	(Entry-level, Mid-level, a	nd High-end configurations; tested on flo	or)					
System Configuration (Mid-level)	Processor Info	Intel® CPU Core i9-12900 16C LGA 2.40 S)	Intel® CPU Core i9-12900 16C LGA 2.40G 30 MB 65W ECC (Intel - –lder Lake S)					
	Memory Info	4* 32GB 4800 SK hy24ynixemory						
	Graphics Info	NVIDIA® RTX A5000						
	Disks/Optical	3*2TB Samsung M.2 SSD; 2*WD 2TB 7200RPM SATA HDD						
	Power Supply	Chicony 700W EPA92						
Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)					
	Idle	3.59	18.5					
	Hard drive Operating (Drive Random Seek)	3.82	20.1					
	Hard drive Operating (Active mode)	3.97	23.6					
System Configuration	Processor Info	Intel® Core i9-12900K 16C 3.20G LGA	30 MB 125W ECC (Intel - –lder Lake-S)					
(High-end)	Memory Info	4* 32GB 4800 SK hy24ynixemory						
	Graphics Info	NVIDIA® RTX A5000						
	Disks/Optical	3*2TB Samsung M.2 SSD; 2*WD 2TB 77	200RPM SATA HDD					
	Power Supply	Chicony 700W EPA92						



System Technical Specifications

Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
	Idle	3.58	18.2
	Hard drive Operating (Drive Random Seek)	3.78	20
	Hard drive Operating (Active mode)	4.05	20.9

Environmental Requirements

Temperature Operating: 5° to 35° C (40° to 95° F)

Non-operating: -40° to 60° C (-40° to 140° F)

Maximum rate of change: 10°C/hr

Humidity Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb

Non-operating: 10% to 90% RH, non-condensing, 35° C maximum wet bulb

Maximum Altitude Operating (with Rotational Hard Drives): 3,048 m (10,000 feet)

Operating (with only Solid-State Drives): 5,000 m (16,404 feet)

Non-operating: 12,192 m (40,000 feet)

Maximum operating temperature is reduced as altitude increases. See

Cooling for details.

Dynamic Shock

Operating: ½-sine: 40g, 2-3ms (~62 cm/sec) Non-operating: ½-sine: 160 cm/s, 2-3ms (~105g)

square: 422 cm/s, 20g

Vibration

Operating random: 0.5g (rms), 5-300 Hz, up to $0.0025g^2/Hz$ Non-operating random: 2.0g (rms), 5-500 Hz, up to $0.0150 g^2/Hz$

Cooling Above 1524 m (5,000 feet) altitude, the maximum operating temperature

is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation,

up to 3048 m (10,000 feet)

NOTE: System enduring or operating beyond the environmental requirement

range is not recommended and may compromise system reliability

permanently.



System Technical Specifications

Physical Security and Serviceability

Access Panel Tool-less

Includes support information

Optical Drive Tool-less, except for Screw-In carrier

Hard Drives Tool-less, except for 2.5" "bay

Expansion Cards Tool-less

Processor Socket Tool-less, except for the processor heatsink **Blue User Touch Points** Yes, on tool-less internal chassis mechanisms

Color-coordinated Cables Yes

and Connectors

MemoryTool-lessSystem BoardScrew-In

Padlock Support Yes (optional): Locks side cover and secures chassis from theft

0.22-in diameter padlock loop at rear of system

Cable Lock Support
Yes, Kensington Cable Lock (optional): Locks side cover and secures chassis from theft

3 mm x 7 mm slot at rear of system

Universal Chassis Clamp

Lock Support

Yes (optional): Locks side cover and locks cables to chassis. Secures chassis from theft and allows

multiple units to be chained together when used with optional cable

Threaded feature at rear of system

Solenoid Lock and Hood

Sensor

Yes (optional)

The Solenoid Hood Lock eliminates the need for a physical key by making the chassis lockable through software and a password. You can also lock and unlock the chassis remotely over the network. The

Sensor Kit detects when the access panel has been removed.

Rear Port Control Cover No

CPUs and Heatsinks A T-15 Torx or flat blade screwdriver is needed to remove the CPU heatsink before the CPU can be

removed. CPU removal is tool-less

Internal Speaker Yes

Power Supply Fans 70mm x 70mm x 25mm 4-wire PWM (non-serviceable)

Access Panel Key Lock No

Integrated Chassis

Handles

Rear Recessed Handle

Power Supply Requires T15 Torx or flat blade screwdriver

PCI Card Retention Yes, rear (all), middle (optional), front (full-length cards with extender)

Service, Support, and Warranty

On-site Warranty and Service¹: Three-years, limited warranty and service offering delivers on-site, next business-day² service for parts and labor and includes free telephone support³ 8am - -pm. Global coverage² ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering. 24/7 operation will not void the HP warranty. Storage devices are not covered under warranty for 24/7 operation except for Enterprise class HDDs.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

NOTE 3: Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries.

HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at:



System Technical Specifications

http://www.hp.com/go/lookuptool. Service levels and response times for HP Care Packs may vary depending on your geographic location.

Certification and Compliance

Environmental Sustainability questions concerning:

- Ecolabels (EPEAT, TCO, etc.)
- ENERGY STAR, California Energy Commission (CEC)
- Compliance with Environmental legislation (EU ErP, China CECP, EU RoHS and other countries)
- Supply Chain Social Environmental Responsibility (SER) (conflict minerals; human rights, etc.)
- Product specific environmental features (material content, packaging content, recycled content, etc.)
- China Energy Label (CEL)

Please contact sustainability@hp.com

For country specific Regulatory Compliance approval documents or Regulatory and Safety questions concerning:

- Declarations of Conformity (for self-service, go to https://www.hp.com/uken/certifications/technical/regulations-certificates.html?jumpid=ex_r135_uk/en/any/corp/hpukmu chev/certificates)
- **GS** Certificates
- Product Safety Certificates (UL. CB. BIS. etc.)
- EMC Certificates, Declarations of Conformity, or Certificates of Conformity (CE, FCC, ICES, etc.)
- **CCC Certificates**
- **Ergonomics**

Please contact techreqshelp@hp.com

BIOS

BIOS 64-bit Services

PCI 3.0 Support

BIOS supports 64-bit Operating systems only.

Full BIOS support for PCI Express through industry standard interfaces.

ATAPI Removable Media Device BIOS Specification Version 1.0.

ATAPI BBS

BIOS Boot Specification v1.01.(Not support)

WMI Support

WMI is Microsoft's'implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM)

and WBEM specifications.

BIOS Boot Spec 1.01+

Provides more control over how and from what devices the workstation will boot. (Not Support)

BIOS Power On

Users can define a specific date and time for the system to power on.

ROM Based Computer Setup Utility (F10)

Review and customize system configuration settings controlled by the BIOS.

System/Emergency ROM

Flash Recovery with

Recovers system BIOS in corrupted Flash ROM.

Video

SMBIOS

Saves BIOS settings to USB flash device in human readable file (HpSetup.txt). **Replicated Setup**

BiosConfigurationUtility.exe utility can then replicate these settings on machines being deployed

without entering Computer Configuration Utility (F10 Setup).

Boot Control

System Management BIOS 3.4, for system management information. Disables the ability to boot from removable media on supported devices.

Memory Change Alert Thermal Alert

Alerts management console if memory is removed or changed. Monitors the temperature state within the chassis. Three modes:

• NORMAL - - ormal temperature ranges.

ALERTED - -xcessive temperatures are detected. Raises a flag so action can be taken to avoid

System Technical Specifications

shutdown or provide for a smoother system shutdown.

• SHUTDOWN - -xcessive temperatures are encountered. Automatically shuts down the computer

without warning before hardware component damage occurs.

Remote ROM Flash Provides secure, fail-safe ROM image management from a central network console.

ACPI (Advanced

Allows the system to enter and resume from low power modes (sleep states).

Management Interface)

Configuration and Power Enables an operating system to control system power consumption based on the dynamic workload. Makes it possible to place individual cards and peripherals in a low-power or powered-off state without

affecting other elements of the system.

Supports ACPI 6.0 for full compatibility with 64-bit operating systems.

Ownership Tag

A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.

Shutdown

Remote Wakeup/Remote System administrators can power on, restart, and power off a client computer from a remote location.

Instantly Available PC

Allows for very low power consumption with guick resume time.

sleep state S3)

(Suspend to RAM - - CPI

Remote System Installation via F12 (PXE

Allows a new or existing system to boot over the network and download software, including the operating system.

2.1) (Remote Boot from Server)

ROM revision levels

Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is available through an industry standard interface (SMBIOS and WMI) so that management SW

applications can use and report this information.

System board revision

level

Allows management SW to read revision level of the system board. Revision level is digitally encoded into the HW and cannot be modified. Assesses system health at boot time with selectable levels of testing.

Start-up Diagnostics (Power-on Self-Test) Auto Setup when new

System automatically detects addition of new hardware.

hardware installed

Keyboard-less Operation The system can be booted without a keyboard.

Localized ROM Setup

Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with

local keyboard mappings.

The user or MIS to set a unique tag string in non-volatile memory. **Asset Tag**

Per-slot Control Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. Adaptive Cooling Control parameters are set according to detected hardware configuration for optimal acoustics. **Pre-boot Diagnostics** (Pre-video) critical errors are reported via beeps and blinks on the power LED.

UEFI Specification

Revision 2.7

ACPI Advanced Configuration and Power Management Interface. Version 6.0 AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b ATA (IDE) **CD Boot** "E" Torito" "ootable CD-ROM Format Specification Version 1.0

EDD Enhanced Disk Drive Specification Version 1.1

BIOS Enhanced Disk Drive Specification Version 3.0(Not support)

Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0 **EHCI**

PCI PCI Local Bus Specification, Revision 2.3

> PCI Power Management Specification, Revision 1.1 PCI Firmware Specification, Revision 3.0, Draft .7 PCI Express Base Specification, Revision 2.0

PCI Express Base Specification, Revision 3.0 PCI Express Base Specification, Revision 4.0

PCI Express Base Specification, Revision 5.0 Ready

POST Memory Manager Specification, Version 1.01 **PMM**

PCI Express

System Technical Specifications

SATA Serial ATA Specification, Revision 1.0a

> Serial ATA 3 Gb/s: Serial ATA Specification, Revision 2.5 Serial ATA 6 Gb/s: Serial ATA Specification, Revision 3.0

SPD JEDEC JESD300-5

Trusted Computing Group TPM Specification Version 2.0 (Infineon SLB 9670). **TPM**

Common Criteria EAL4+ certified.

FIPS 140-2 Certification TCG TPM Certified products list:

http://www.trustedcomputinggroup.org/certification/tpm-certified-products/

Universal Host Controller Interface Design Guide, Revision 1.1 UHCI

USB Universal Serial Bus Revision 1.1 Specification

> Universal Serial Bus Revision 2.0 Specification Universal Serial Bus Revision 3.1 Specification Universal Serial Bus Revision 3.2 Specification

SMBIOS System Management BIOS Reference Specification, Version 3.4

External BIOS simulator found at: http://csrsml.itcs.hp.com/

Social and Environmental Responsibility

Eco-Label Certifications & Declarations

This product is low halogen except for configurations that include HP Z Turbo Quad Pro PCIe TLC SSD. CRU QX 428 & QX448 removable storage frames, ConnectX-6 DX Amphenol 10 & 25 Gb Transceivers, Broadcom 5720-2P NIC Card, power cords, cables, and peripherals. Service parts obtained after purchase may not be Low Halogen.

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- **US ENERGY STAR®**
- US Federal Energy Management Program (FEMP)
- EPEAT® Gold with Climate+ registered. See www.epeat.net for registration status and tier levels by country
- TCO Certified
- China Energy Conservation Program (CECP)
- China State Environmental Protection Administration (SEPA)
- Taiwan Green Mark
- Korea Eco-label
- Japan PC Green label*

Sustainable Impact **Specifications**

- Product Carbon Footprint (hp.com)
- Ocean-bound plastic in System FAN, CPU FAN and Speaker
- 50% post-consumer recycled plastic
- Low halogen
- Outside Box and corrugated cushions are 100% sustainably sourced and recyclable
- Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable

System Configuration The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".

Energy Consumption (in accordance with US **ENERGY STAR® test**

method) 115VAC, 60Hz 230VAC, 50Hz 100VAC, 50Hz

System Technical Specifications

QuickSpecs

Normal Operation (Sort idle)	34.16 W	34.01 W	34.39 W
Normal Operation (Long idle)	32.77 W	32.74 W	33.15 W
Sleep	2.57 W	2.54 W	2.57 W
Off	0.67 W	0.68 W	0.67 W

NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family . HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	116.8 BTU/hr	116.3 BTU/hr	117.6 BTU/hr
Normal Operation (Long idle)	112.1 BTU/hr	112 BTU/hr	113.4 BTU/hr
Sleep	8.8 BTU/hr	8.7 BTU/hr	8.8 BTU/hr
Off	2.3 BTU/hr	2.3 BTU/hr	2.3 BTU/hr

*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Longevity and Upgrading

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the

Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive -2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product is 94.8% recycle-able when properly disposed of at end of life.

Packaging Materials	External:	PAPER/Corrugated	1214 g
		PAPER/Molded Pulp	890 g
	Internal:	PLASTIC/Polyethylene low density - DPE	- 40 g

The plastic packaging material contains at least 0.0% recycled content.

The corrugated paper packaging materials contains at least 62.5% recycled content.

RoHS Compliance

HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.



System Technical Specifications

We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.

We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.

To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these quidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.



System Technical Specifications

Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP 0EM customers who integrate and re-sell HP equipment.

HP, Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

footnotes

- Percentage of ocean-bound plastic contained in each component varies by product
- Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.
- External power supplies, WWAN modules, power cords, cables and peripherals excluded.
- 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.
- Fiber cushions made from 100% recycled wood fiber and organic materials.

SATA Hard Drives for H	ΙP
Workstations	

500GB SATA 7200 rpm 6Gb/s 3.5""DD

Capacity 500GB Protocol **SATA** Controller AHCI

Height 1 in; 2.54 cm

Width **Media Diameter** 3.5 in: 8.9 cm **Physical Size** 4 in; 10.17 cm

Up to 600MB/s *

Interface Serial ATA (6.0Gb/s), NCO enabled

Synchronous Transfer

Rate (Maximum)

Buffer 32MB

Seek Time (typical reads, Single Track 2 ms * includes controller **Average** 11 ms * overhead, including **Full Stroke** 21 ms * settling)

Rotational Speed 7,200 rpm **Logical Blocks** 976,773,168

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

1TB	SAT	A 720	0 rpm
6Gb	/s 3.	5" "D	D

Capacity	1TB
Protocol	SATA
Controller	AHCI

Height 1 in; 2.54 cm

Width **Media Diameter** 3.5 in: 8.9 cm **Physical Size** 4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Up to 600 MB/s *

Buffer 64MB

Seek Time (typical reads, Single Track 2 ms * includes controller **Average** 11 ms * overhead, including **Full Stroke** 21 ms *

settling)

Logical Blocks

Rotational Speed 7,200 rpm 1,953,525,168

41° to 131° F (5° to 55° C) **Operating Temperature**

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

2TB SATA 7200 rpm 6Gb/s 3.5" "DD

Capacity 2TB **Protocol** SATA Controller **AHCI**

Annualized Failure Rate

(based on Rated POH) <0.62% Height 1 in; 2.54 cm

Width **Media Diameter** 3.5 in; 8.9 cm

^{*}Actual performance may vary.

^{*}Actual performance may vary.

	Physical Size	4 in; 10.17 cm
Interface	Serial ATA (6.0 Gb/s), NCQ Enabled	

Up to 600MB/s *

Synchronous Transfer

Rate (Maximum)

Buffer 64MB

Seek Time (typical reads, Single Track 2.0 ms * includes controller Average 11 ms * overhead, including **Full Stroke** 21 ms * settling)

Rotational Speed 7,200 rpm **Logical Blocks** 3,907,029,168

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

1TB SATA 7200 rpm
6Gb/s 3.5" "DD
(Enterprise Class)

Capacity	1TB
Height	1 in; 2.54 cm
Protocol	SATA
Controller	AHCI
Reliability	2.0M hours
Rated Power On Hours	8760/yr

Annualized Failure Rate (based on Rated POH)

<0.62%

Width **Media Diameter** 3.5 in; 8.9 cm

Interface Serial ATA (6.0 Gb/s), NCQ Enabled

Synchronous Transfer

Rate (Maximum)

Up to 600MB/s *

Physical Size

4 in: 10.17 cm

Buffer 128MB

Seek Time (typical reads. **Single Track** 0.32ms* includes controller **Average** 7.45ms* overhead, including **Full Stroke** 14.2ms*

settling)

Rotational Speed 7,200 rpm

Operating Temperature 41° to 140° F (5° to 60° C)

Performance Sequential Read up to 226MB/s* up to 226MB/s* **Sequential Write**

Enterprise Class Features High Reliability

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

2TB SATA 7200 rpr	ľ
6Gb/s 3.5" "DD	
(Enterprise Class)	

Capacity	2TB
Protocol	SATA
Controller	AHCI
Reliability (MTBF)	2.0M hours
Rated Power On Hours	8760/yr



^{*}Actual performance may vary.

^{*}Actual performance may vary.

Annualized Failure Rate < 0.62%

(based on Rated POH)

Rated for 24/7/365

Operation

Physical Size (Height)1 in; 2.54 cmPhysical Size (Width)4 in; 10.17 cmMedia Diameter3.5 in; 8.9 cm

Interface Serial ATA (6Gb/s), NCQ enabled

Up to 600MB/s*

Synchronous Transfer

Rate (Maximum)

128MB

Seek Time (typical reads, includes controller overhead, including

settling)

Buffer

Single Track 0.7ms* Average 8.5ms*

Full Stroke 15.7ms*

Rotational Speed 7,200 rpm

Operating Temperature 41° to 131° F (5° to 55° C)

Performance Sequential Read up to 226MB/s*
Sequential Write up to 226MB/s*

Enterprise Class Features High Reliability

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

4TB SATA 7200 rpm 6Gb/s 3.5" "DD (Enterprise Class) Capacity4TBProtocolSATAControllerAHCI

Reliability 2.0M hours **Rated Power On Hours** 8760/yr **Annualized Failure Rate** <0.62%

(based on Rated POH)

Rated for 24/7/365

Operation

Physical Size (Height)1 in; 2.54 cmPhysical Size (Width)4 in; 10.17 cmMedia Diameter3.5 in; 8.9 cmPhysical Size4 in; 10.17 cm

Interface Serial ATA (6Gb/s), NCQ enabled

Up to 600MB/s*

Synchronous Transfer

Rate (Maximum)

. . _

Buffer 256MB

Seek Time (typical reads,
includes controller
overhead, including
settling)Single Track
Average
Full Stroke0.7ms*8.5ms*
9.57ms*

Rotational Speed 7,200 rpm

Operating Temperature 41° to 131° F (5° to 55° C)

^{*}Actual performance may vary.

Performance Sequential Read up to 226MB/s*
Sequential Write up to 226MB/s*

Enterprise Class High Reliability

Features

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

8TB SATA 7200 rpm 6Gb/s 3.5" "DD (Enterprise Class)

Capacity 8TB
Protocol SATA
Controller AHCI
Reliability 2.0M hours

Width Media Diameter 3.5 in; 8.9 cm Physical Size 4 in; 10.17 cm

Up to 600MB/s [1]

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Buffer

256MB

Seek Time (typical reads, includes controller overhead, including settling)

Single Track

Average

Full Stroke

Rotational Speed 7,200 rpm

Operating Temperature 41° to 140° F (5° to 60° C)

PerformanceSequential Readup to $226MB/s^1$ Sequential Writeup to $226MB/s^1$

Enterprise Class Features High Reliability

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

500GB SATA 7.2K SED 2.5" "DD

Capacity 500GB Protocol SATA

Height 0.275 in; 0.7 cm

Width Media Diameter 2.5 in; 6.36 cm

Physical Size 2.75 in; 6.99 cm

25ms (Typical)*

0.7ms*

8.5ms*

15.7ms*

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer Up to 600MB/s*

Rate (Maximum)

Buffer 64MB

Seek Time (typical reads, includes controller overhead, including 5 u.s. 1 ms*

Average 4.2ms*

Yes

Full Stroke

settling)

Rotational Speed 7,200 rpm

Operating Temperature 32° to 131° F (0° to 60° C)

Self-Encrypting Drive

Support

Technical Specifications - Hard Drives

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv PCIE-4X4 Capacity 512GB TLC PCIe SSD Protocol

(Z2G9)

Capacity 512GB Protocol PCle

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 150TBW (TB Written)

Reliability (MTBF) 1.5M hours

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 178° F (0° to 81° C)

Performance Sequential Read 6400MB/s*

Sequential Write 3400MB/s*
Random Read 600K IOPS*
Random Write 600K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv PCIE-4X4 Capacity 1TB TLC PCIe SSD (Z2G9) Protocol

Capacity 1TB Protocol PCle

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 300TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 178° F (0° to 81° C)

Performance Sequential Read 6500MB/s*

Sequential Write 5000MB/s*
Random Read 800K IOPS*
Random Write 800K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv PCIE-4X4 Capacity 2TB TLC PCIe SSD (Z2G9) Protocol

Capacity 2TB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 500TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 4.0 x4 electrical



^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

32° to 178° F (0° to 81° C) Operating Temperature

Performance Sequential Read 6500MB/s*

> Sequential Write 5000MB/s* **Random Read** 800K IOPS* 800K IOPS* **Random Write**

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv PCIE-4X4 Capacity

4TB

TLC PCIe SSD

4TB **Protocol PCIe**

Form Factor M.2 in native Slot on motherboard

Controller NVMe **NAND Type** 3D TLC

Endurance 600TBW (TB Written)

Reliability (MTBF) 1.5M Hours

Interface PCI Express 4.0 x4 electrical **Operating Temperature** 32° to 178° F (0° to 81° C)

Performance Sequential Read 6500MB/s*

> **Sequential Write** 5000MB/s* **Random Read 700K IOPS* Random Write 700K IOPS***

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP	Z	T	ur	bo	D	rv	P	CI	E
Cal	n/	w	1	4TI	R				

Gen4x4 4TB **TLC PCIe SED OPAL2**

Capacity 4TB **Protocol PCIe**

Form Factor M.2 in native Slot on motherboard

Controller NVMe **NAND Type** 3D TLC

Endurance 600TBW (TB Written) Interface PCI Express 4.0 x4 electrical **Operating Temperature** 32° to 178° F (0° to 81° C)

Performance Sequential Read 6500MB/s*

> Sequential Write 5000MB/s* **Random Read 700K IOPS* Random Write 700K IOPS***

Self-Encrypting Drive OPAL2

Support

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv 512GB Capacity 512GB

> **PCle Protocol**



^{*}Actual performance may vary.

^{*}Actual performance may vary.

600K IOPS*

600K IOPS*

Technical Specifications - Hard Drives

TLC PCIe SED OPAL2 (Z2G9)	Form Factor	M.2 in native Slot on	motherboard
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	150TBW (TB Written)
	Reliability	1.5M Hours	
	Interface	PCI Express 4.0 x4 el	ectrical
	Operating Temperature	32° to 178° F (0° to 8	31° C)
	Performance	Sequential Read	6400MB/s*
		Sequential Write	3400MB/s*

Self-Encrypting Drive OPAL2

*Actual performance may vary. NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Random Read

Random Write

HP Z Turbo Drv 1TB TLC PCIe SED	Capacity	1TB		
	Protocol	PCle		
OPAL2 (Z2G9)	Form Factor	M.2 in native Slot on mo	otherboard	
	Controller	NVMe		
	NAND Type	3D TLC		
	Endurance 300TBW (TB Written) Reliability 1.5M Hours			
	Reliability	1.5M Hours		
	Interface PCI Express 4.0 x4 electrical			
	Operating Temperature	32° to 178° F (0° to 81°	C)	
	Performance	Sequential Read	6500MB/s*	
		Sequential Write	5000MB/s*	
		Random Read	800K IOPS*	
		Random Write	800K IOPS*	
	Self-Encrypting Drive Support	OPAL2		

^{*}Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv 2TB	Capacity	2TB	
TLC PCIe SED	Protocol	PCle	
UPAL2 (22G9)	Form Factor Controller NAND Type Endurance Reliability M.2 in native Slot on motherboard NVMe 3D TLC 500TBW (TB Written)		
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	Controller NVMe NAND Type 3D TLC Endurance 500TBW (TB Written) Reliability 1.5M Hours	
	Reliability	1.5M Hours	
	Interface	PCI Express 4.0 x4 elec	trical
	Operating Temperature	32° to 178° F (0° to 81°	' C)
	Performance	Sequential Read	6500MB/s*



Support

Technical Specifications - Hard Drives

Sequential Write5000MB/s*Random Read800K IOPS*Random Write800K IOPS*

Self-Encrypting Drive Support

OPAL2

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

256GB	2280	PCIe-4x4
Value I	M.2 SS	SD .

Capacity 256GB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 150TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3100MB/s*
Sequential Write 1400MB/s*
Random Read 200K IOPS*
Random Write 400K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

51	2GB	2280	PCI	e-4x4
Va	due	M 2 S	מו	

Capacity 512GB Protocol PCle

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 300TBW (TB Written)

Reliability 1.5M Hours

InterfacePCI Express 4.0 x4 electricalOperating Temperature32° to 158° F (0° to 70° C)

Performance Sequential Read 3400MB/s*

Sequential Write 2500MB/s*
Random Read 380K IOPS*
Random Write 430K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

1TB 2280 PCIe-4x4 Value	Capacity	1TB
M.2 SSD	Protocol	PCle

Form Factor M.2 in native Slot on motherboard

Controller NVMe

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

NAND Type 3D TLC

Endurance 400TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3400MB/s*

Sequential Write 2500MB/s*
Random Read 500K IOPS*
Random Write 440K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.



^{*}Actual performance may vary.

AMD Radeon™ Pro W6600 8GB Graphics **Form Factor** Single slot, full-height, 9.5" length

Graphics Controller Navi23 architecture Power: 122 Watts

Cooling Solution: Active Fan Heatsink

Bus Type PCI Express 4.0 x8 8GB GDDR6 Memory Memory

> Memory Bandwidth: 224 GB/s Memory Interface: 128 bit

4x DisplayPort™ 1.4 with DSC **Connectors**

- HDR Ready

Supports Multi-Stream Transport (MST)

Max simultaneous

displays

@ 60Hz with HDR Enabled 4x @ 3840x2160px (4K) 4x @ 5120x2880px (5K) 1x @ 7680x4320px (8K)

Shading Architecture DirectX 12 Shader Model 6.5

Supported Graphics APIs

DirectX®12 Ultimate OpenGL® 4.6

OpenCL™ 2.1 Vulkan™ 1.2

Available Graphics

Drivers

Windows 10 64-bit Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

AMD Radeon™ Pro W6800 Form Factor

32GB Graphics

Double slot, full-height, 10.5" length

Graphics Controller Navi21 architecture

Power: 261 Watts

Cooling Solution: Active Fan Heatsink

Bus Type PCI Express 4.0 x16 Memory 8GB GDDR6 Memory

> Memory Bandwidth: 512 GB/s Memory Interface: 256 bit

Connectors 6x Mini-DisplayPort™ 1.4 with DSC

- HDR Ready

- Supports Multi-Stream Transport (MST)

Max simultaneous

displays

@ 60Hz with HDR Enabled 6x @ 3840x2160px (4K) 6x @ 5120x2880px (5K)

2x @ 7680x4320px (8K)

Shading Architecture

DirectX 12 Shader Model 6.5

Supported Graphics APIs DirectX®12 Ultimate

> OpenGL® 4.6 OpenCL™ 2.1 Vulkan™ 1.2



NVIDIA® T400 4GB Graphics

Form Factor Single Slot, Low Profile (2.7" H x 6.1" L)

Graphics Controller Turing architecture Max Power: 30 Watts

Cooling Solution: Active fan heatsink

Bus Type PCI Express 3.0 x16 Memory 4GB GDDR6 Memory

> Memory Bandwidth: 80 GB/s Memory Interface: 64 bit

Connectors 3x mDP (Mini DisplayPort™) 1.4 Connectors

Max simultaneous

displays - 3x 3840 x 2160 @ 120Hz

- 3x 5120 x 2880 @ 60Hz

supports Multi-Stream Transport (MST)

Shading Architecture

DirectX 12 Shader Model 5.1

Supported Graphics APIs OpenGL 4.6

DirectX 12 Vulkan 1.2

API support includes: CUDA, OpenCL 1.2 Windows 10 64-bit

Available Graphics

Drivers

Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® T600 4GB Graphics*

Form Factor Single Slot, Low Profile (2.7" H x 6.1" L)

Graphics Controller Turing architecture Max Power: 40 Watts

Cooling Solution: Active fan heatsink

Bus Type PCI Express 3.0 x16 Memory 4GB GDDR6 Memory

> Memory Bandwidth: 160 GB/s Memory Interface: 128 bit

Connectors 4x mDP (Mini DisplayPort™) 1.4 Connectors

Max simultaneous - 4x 3840 x 2160 @ 120Hz displays - 4x 5120 x 2880 @ 60Hz

- 2x 7680 x 4320 @ 60Hz - supports Multi-Stream Transport (MST)

Shading Architecture DirectX 12 Shader Model 5.1

Supported Graphics APIs OpenGL 4.6

> DirectX 12 Vulkan 1.2

API support includes: CUDA, OpenCL 1.2

Available Graphics

Windows 10 64-bit **Drivers** Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

*May go End of Life in late 2022

AMD® Radeon™ RX 6400 4GB Graphics **Form Factor** Single slot, Low Profile (2.8" H x

6.3" L)

Weight: 155g

Graphics Controller Radeon™ RX 6400

Max Power: 53W

Cooling Solution: Active axial fan

Architecture: RDNA™ 2

Bus Type PCI Express x4 Gen4
Memory Size: 4GB GDDR6

Interface: 64-bit

Bandwidth: up to 128 GB/s

Connectors DP (DisplayPort™) 1.4 + HDMI 2.1 **Max simultaneous** - up to 4x 5120 x 2880 x 24 bpp @

displays

60Hz

Shading Architecture

Microsoft DirectX 12 Shader Model

5.1

Supported Graphics APIs OpenGL® 4.6

DirectX® 12 Ultimate

Vulkan™ 1.1

API support includes: OpenCL™ 2.2

Available Graphics

Drivers

Microsoft Windows 10 64-bit, Windows 11 64-bit

HP qualified drivers may be preloaded or the latest prosumer graphics

drivers are available from the AMD.com

Notes This is a Prosumer or Consumer graphics card, and not a Professional

graphics card. As such, it does not have formal professional application validation, but is intended per AMD to function properly for game development, real-time engine, and many prosumer application workloads. Customers using Prosumer or Consumer graphic cards with axial fan cooling solutions are likely to experience higher acoustics in comparison with Professional graphic cards that use blower fan cooling.

NVIDIA® T1000 4GB Graphics

Form Factor Single Slot, Low Profile (2.7" H x

6.1" L)

Graphics Controller Turing architecture

Max Power: 50 Watts

Cooling Solution: Active fan heatsink

Bus Type PCI Express 3.0 x16 **Memory** 4GB GDDR6 Memory

Memory Bandwidth: 160 GB/s Memory Interface: 128 bit

Connectors 4x mDP (Mini DisplayPort™) 1.4 Connectors

Max simultaneous - 4x 3840 x 2160 @ 120Hz

displays - 4x 5120 x 2880 @ 60Hz

- 2x 7680 x 4320 @ 60Hz

- supports Multi-Stream Transport (MST)

Shading Architecture DirectX 12 Shader Model 5.1

Supported Graphics APIs OpenGL 4.6

DirectX 12 Vulkan 1.2

API support includes: CUDA, OpenCL 1.2 Windows 10 64-bit

Available Graphics

Drivers Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® T1000 8GB Graphics

Form Factor Single Slot, Low Profile (2.7" H x

6.1" L)

Graphics Controller Turing architecture

Max Power: 50 Watts

Cooling Solution: Active fan heatsink

Bus TypePCI Express 3.0 x16Memory8GB GDDR6 Memory

Memory Bandwidth: 160 GB/s Memory Interface: 128 bit

Connectors 4x mDP (Mini DisplayPort™) 1.4 Connectors

Max simultaneous

displays - 4x 5120 x 2880 @ 60Hz

- 2x 7680 x 4320 @ 60Hz

- 4x 3840 x 2160 @ 120Hz

- supports Multi-Stream Transport (MST)

Shading Architecture

DirectX 12 Shader Model 5.1

Supported Graphics APIs OpenGL 4.6

DirectX 12 Vulkan 1.2

API support includes: CUDA, OpenCL 1.2 Windows 10.64-bit

Available Graphics

Drivers

Windows 10 64-bit Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® RTX 2000 Ada Form Factor Half Height Dual Slot (2.7" Height x

6.7" Length)

Max Power Consumption 70W

Technical Specifications - Graphics

GPU Memory 16GB GDDR6

Memory Bandwidth: 224 GB/s

Memory Width: 128-bit

Connectors 4x Mini DisplayPort 1.4a

Maximum Resolution 4x 4096 x 2160 @ 120 Hz

4x 5120 x 2880 @ 60 Hz 2x 7680 x 4320 @ 60 Hz

Bus Type PCI Exress 4.0 x8

Avaliable Drivers Windows 10

Windows 11

NVIDIA® RTX™ A2000 12GB Graphics Form Factor Low-Profile Double Slot (2.7" H x

6.1" L)

Graphics Controller Ampere architecture

Power: 70 Watts

Cooling: Active Fan Heatsink

Bus Type PCI Express 4.0 x16
Memory 12GB GDDR6 memory

Memory Bandwidth: 288 GB/s Memory Interface: 192 bit

Support Error-correcting code (ECC)

Connectors 4x mDP (Mini DisplayPort™) 1.4 Connectors

Max simultaneous

displays

4x 4096 x 2160 @ 120 Hz, 4x 5120 x 2880 @ 60 Hz 2x 7680 x 4320 @ 60 Hz

Shading Architecture Shader Model 6.5

Supported Graphics APIs OpenGL 4.6

DirectX 12 Vulkan 1.2

API support includes: CUDA, OpenCL 1.2

Available Graphics

Drivers

Windows 10 64-bit Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® RTX 4000 Ada Form Factor Full-Height Triple Slot (4.4" Height

x 11.5" Length)

Max Power Consumption 130W

GPU Memory 20GB GDDR6

Memory Bandwidth: 360 GB/s Memory Width: 160-bit

Connectors 4x DisplayPort 1.4a

Requires: 1x 16-pin CEM 5 power connector (adapter may be needed)

Maximum Resolution 4x @ 4096 x 2160 @ 120Hz

4x @ 5120 x 2880 @ 60Hz 2x @ 7680 x 4320 @ 60Hz



Bus Type PCI Exress 4.0 x16 **Avaliable Drivers** Windows 10

Windows 11

NVIDIA® RTX™ A4000

16GB Graphics

Form Factor Full Height Single Slot (9.5"

Length)

Graphics Controller Ampere architecture

Power: 140 Watts

Cooling: Active Fan Heatsink

Bus Type PCI Express 4.0 x16 Memory 16GB GDDR6 memory

Memory Bandwidth: 448 GB/s Memory Interface: 256 bit

Support Error-correcting code (ECC)

Connectors Max simultaneous

displays

4x 4096 x 2160 @ 120 Hz. 4x 5120 x 2880 @ 60 Hz. 2x 7680 x 4320 @ 60 Hz

4x DP 1.4 Connectors

Shading Architecture Shader Model 6.5

Supported Graphics APIs

OpenGL 4.6 DirectX 12 Vulkan 1.2

API support includes: CUDA, OpenCL 1.2 Windows 10 64-bit

Available Graphics

Drivers

Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

http://welcome.hp.com/country/us/en/support.html

NVIDIA® RTX™ A4500 **20GB Graphics**

Form Factor

Full Height Double Slot (10.5"

Length)

Graphics Controller

Ampere architecture Power: 200 Watts

Cooling: Active Fan Heatsink

Bus Type PCI Express 4.0 x16 Memory 20GB GDDR6 memory

Memory Bandwidth: 640 GB/s Memory Interface: 320 bit

Support Error-correcting code (ECC)

Connectors 4x DP 1.4 Connectors

Max simultaneous 4x 4096 x 2160 @ 120 Hz. displays

4x 5120 x 2880 @ 60 Hz, 2x 7680 x 4320 @ 60 Hz

Shading Architecture Shader Model 6.5

Supported Graphics APIs OpenGL 4.6

DirectX 12 Vulkan 1.2



Technical Specifications - Graphics

API support includes:

CUDA, OpenCL 1.2

Available Graphics

Drivers

Windows 10 64-bit Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® RTX™ A5000 24GB Graphics Form Factor Full Height Double Slot (10.5"

Length)

Graphics Controller Ampere architecture

Power: 230 Watts

Cooling: Active Fan Heatsink

Bus Type PCI Express 4.0 x16 **Memory** 24GB GDDR6 memory

Memory Bandwidth: 768 GB/s Memory Interface: 384 bit

Support Error-correcting code (ECC)

Connectors 4x DP 1.4 Connectors

Max simultaneous

displays

4x 4096 x 2160 @ 120 Hz, 4x 5120 x 2880 @ 60 Hz, 2x 7680 x 4320 @ 60 Hz

Shading Architecture Shader Model 6.5

Supported Graphics APIs

OpenGL 4.6 DirectX 12

Vulkan 1.2 API support includes:

Available Graphics

Drivers

Windows 10 64-bit Windows 11 64-bit

CUDA, OpenCL 1.2

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

AMD® Radeon™ Pro W7600 8GB Form Factor Full-Height Single Slot (4.38"

"eight x 9.5" "ength)

Max Power Consumption 130W GPU Memory 8GB GDDR6

Memory Bandwidth: 288 GB/s

Memory Width: 128-bit

Connectors 4x DP 2.1

Requires: 1x 6-pin PCle Aux Power

Maximum Resolution 4x @ 3840x2160 (4K)

4x @ 5120x2880 (5K) 2x @ 7680x4320 (8K)

Bus Type PCI Express 4.0 x8

Technical Specifications - Graphics

Available Graphics Windows 10 **Drivers** Windows 11

Form Factor Full-Height Single Slot (4.38"

MD® Radeon™ Pro W7500 8GB "eight x 8.5" "ength)

Max Power Consumption 70W

GPU Memory 8 GB GDDR6

> Memory Bandwidth: 173 GB/s Memory Width: 128-bit

Connectors 4x DP 2.1

Maximum Resolution 4x @ 3840x2160 (4K)

> 4x @ 5120x2880 (5K) 2x @ 7680x4320 (8K) PCI Express 4.0 x8

Bus Type Available Graphics Windows 10

Drivers Windows 11

AMD Radeon™ **RX 6700 XT**

Dual slot, Full Length (254mm L x **Form Factor**

38mm W x 108.65mm H)

AMD Radeon™ RX 6700 XT Graphics **Graphics Controller**

GPU: 2560 Navi2 Stream Processors

Memory: 12GB GDDR6

Power: 230 Watts, Standard graphics 8pin + 6pin auxiliary power

Cooling: Active, Dual Axial fan

Bus Type PCI Express 4.0 x16

Connectors 3DP 1.4 + HDMI 2.1 Outputs **Maximum Resolution** DisplayPort™ 1.4 with DSC:

- up to 4x 5210 x 3200 x 24 bpp @ 60Hz, uncompressed

- up to 7680 x 4320, compressed Display Outputs 3 DP + 1 HMDI

Shading Architecture Microsoft DirectX 12 Shader Model 6.1

Supported Graphics APIs OpenGL 4.6

DirectX 12 Feature Level 12_1

Vulkan 1.1 OpenCL 2.2

Available Graphics

Windows 11

Drivers Linux® 64-bit (selected distributions)

Typically, latest drivers will be available from amd.com

Notes: This is a Prosumer or Consumer graphics card, and not a Professional graphics card. As such, it does not have formal professional application validation, but is intended per AMD to function properly for game development, real-time engine, and many prosumer application workloads. Customers using Prosumer or Consumer graphic cards are likely to experience higher acoustics in comparison with Professional graphic cards. The higher acoustics observed with non-professional graphics is expected, as HP Workstations' designs do not have control in this area.

HP 9.5mm Slim DVD Writer

Description 9.5mm height, tray-load **Mounting Orientation** Either horizontal or vertical

Interface Type SATA/ATAPI

Dimensions (WxHxD) 128 x 9.5 x 127mm

Supported Media Types DVD+R

DVD+RW



DVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-R

Disc Capacity DVD-ROM 8.5 GB DL or 4.7 GB standard

Access Times Full Stroke DVD < 200 ms (seek)

Full Stroke CD < 200 ms (seek)

Maximum Data Transfer

Rates

CD ROM Read CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

DVD ROM Read DVD+RW Up to 8X

DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X

Power Source SATA DC power receptacle

DC Power Requirements 5 VDC ± 5%-100 mV ripple p-p

DC Current 5 VDC -< 800 mA typical, <1600 mA maximum

10% to 80%

Operating Environmental Temperature 41° to 122° F (5° to 50° C)

(all conditions non-

condensing)

Relative Humidity

Maximum Wet Bulb 84° F (29° C)

Temperature

Operating Systems

Supported

Windows 11, Windows 10, Windows 7 Professional 64-bit,

Windows Vista Business 64*, Windows 2000.

Linux®.

Kit Contents HP SATA DVD Writer drive, installation quide.

Approvals USB-IF, WHQL, Compliant with USB Mass Storage Class Bulk only Transport

Specification Rev. 1.0,

Compliant Intel Front Panel I/O Connectivity Design Guide V. 1.3, FCC, CE,

BSMI, C-Tick, VCCI, MIC, cUL, TUVT

NOTE: Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

HP 9.5mm Slim DVD-ROM Description

Drive

Description 9.5mm height, tray-load **Mounting Orientation** Either horizontal or vertical

Interface TypeSATA / ATAPIDimensions (WxHxD)128 x 9.5 x 127mm

Disc Capacity DVD-ROM Single layer: Up to 4.7 GB

Double layer: Up to 8.5 GB

Technical Specifications - Graphics

Access Times DVD-ROM Single Layer < 110 ms (typical)

> **CD-ROM Mode 1** < 110 ms (typical) **Full Stroke DVD** < 230 ms (typical) **Full Stroke CD** < 220 ms (typical)

Power Source SATA DC power receptacle

> **DC Power Requirements** 5 VDC ± 5%-100 mV ripple p-p

DC Current 5 VDC - <800mA typical, < 1600 mA maximum

Operating Environmental Temperature 41° to 122° F (5° to 50° C)

(all conditions non-

condensing)

Relative Humidity 10% to 80% **Maximum Wet Bulb** 84° F (29° C)

Temperature

Operating Systems Supported

Windows 11, Windows 10, Windows 7 Professional 64-bit,

Windows Vista Business 64*, Windows 2000.

Linux®.

Kit Contents 9.5mm Slim DVD-ROM Drive, slim SATA data/power cable, installation

quide

Approvals USB-IF, WHQL, Compliant with USB Mass Storage Class Bulk only Transport

Specification Rev. 1.0,

Compliant Intel Front Panel I/O Connectivity Design Guide V. 1.3, FCC, CE,

BSMI, C-Tick, VCCI, MIC, cUL, TUVT

NOTE: Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.



Integrated Intel® I219LM Connector

PCIe GbE Controller (Intel® vPro® with Intel® AMT 16.01) Connector RJ-45

Cabling Twisted pair up to 100m

Controller Intel® I219LM GbE platform LAN connect networking controller

Memory 3 KB Tx and 3KB Rx FIFO packet buffer memory

Data Rates Supported 10/100/1000 Mbps

Compliance 802.1as/1588, 802.1p, 802.1Q, 802.3, 802.3ab, 802.3az, 802.3i, 802.3u,

802.3z

Bus Architecture PCI Express and SMBus

Data Transfer Mode PCIe-based interface for active state operation (S0 state) and SMBus for

host and management traffic (Sx low power state)

Power Requirement Requires 3.3V (integrated regulators for core Vdc)

Boot ROM Support Yes

Network Transfer Mode Full-duplex; Half-duplex

Network Transfer Rate 10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps

Management Capabilities vPro®, WOL, auto MDI crossover, PXE, Muti-port teaming, RSS, ACPI,

Advanced cable diagnostic, loopback modes,

AMT 16.0 support, Circuit Breaker, VLAN, Multicast Listener Discovery

(MLD)

¹Requires activation and a system with a corporate network connection, an Intel® AMT enabled chipset, and network hardware and software. For notebooks, Intel AMT may be unavailable or limited over a host OS-based VPN, when connecting wirelessly, on battery power, sleeping, hibernating, or powered off. Results dependent upon hardware, setup, and configuration. For more information, visit: https://www.intel.com/content/www/us/en/architecture-and-technology/intel-active-management-technology.html

HP 1-Port 1GbE Flex IO NIC

Connector RJ-45

Cabling 1GbE over Category 5e (or better) up to 100m

Controller Realtek RTL8153

Data Rates Supported 10/100/1000 Mbps

Compliance 802.3 (LAN)

802.3u (100BASE-TX) 802.3ab (1000BASE-T) 802.3x (Ethernet Flow Control)

802.1Q (Virtual LAN)

802.3az (Energy Efficient Ethernet)

Bus Architecture USB

Power Requirement Requires 3.3V (integrated regulators for core Vdc)

Boot ROM Support Yes

Network Transfer Mode Full-duplex; Half-duplex

Network Transfer Rate 10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps



100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps

Operating Temperature

32° to 131° F (0° to 55° C)

Dimensions (HxW)

1.5 in x 1.5 in. x 0.75 in (3.81 cm x 3.81 cm x 1.9 cm)

Operating System Driver Windows 11 64-bit

Support

Windows 10 64-bit

Linux®

Intel® X550-T2 2-Port **10GbE NIC**

Connector Dual-port RJ-45

Cabling 10GbE: Cat6a (or better) up to 100m

5GbE and below: Cat5e (or better) up to 100m

Controller Intel® Ethernet Controller X550 **Network Transfer Rates**

Supported

10GbE, 5GbE, 2.5GbE, 1GbE, 100MbE

Data Path Width PCIe Gen3x4

Power Requirement 11.2W (typical) 13.0 (Maximum)

Operating Temperature 32° to 131° F (0° to 55° C) Dimensions (HxW) 5.1 x 2.7 in (without brackets)

Operating System Driver Windows 11 64-Bit

Support

Windows 10 64-bit

Linux®

Kit Contents • Intel® X550-T2 2-Port 10GbE NIC with standard height bracket

attached

 Low-profile bracket Product Literature

Intel® I350-T4 4-Port 1GbE NIC

Connector 4 RJ-45

Cabling Cat5e (or better) up to 100m Controller Intel® Ethernet I350 Controller

Network Transfer Rates

Supported

1GbE, 100MbE, 10MbE

Data Path Width PCIe Gen2.1x4 **Power Requirement** 5W (typical)

Operating Temperature 32° to 131° F (0° to 55° C)

Dimensions (HxW) 2.75 x 5.5 inches (without brackets)

Operating System Driver Windows 11

Support

Windows 10

Linux®

Kit Contents Intel® 1350-T4 4-Port 1GbE NIC with standard height bracket attached

> Low-profile bracket **Product Literature**

HP Flex 1GbE Fiber LC Single Port

Connector Fiber

Cabling 1GbE over Category OM1 (or better) up to 100m

Controller Microchip LAN7801

Data Rates Supported

100/1000 Mbps

Compliance

IEEE 802.1p priority encoding/tagging (QoS, CoS)

IEEE 802.1q VLAN tagging IEEE 802.3x flow control

Bus Architecture USB

Power Requirement

Requires 3.3V (integrated regulators for core Vdc)

Boot ROM Support Ye

Network Transfer Mode Full-duplex; Half-duplex

Network Transfer Rate 100BASE-X (half-duplex) 100 Mbps 1000BASE-X (half-duplex) 1000 Mbps

1000BASE-X (full-duplex) 2000 Mbps

Operating Temperature 3

32° to 158° F (0°C to 70°C)

calvin 1.5 in x 1.7 in. x 0.7 **Operating System Driver** Windows 11 64-Bit

Support

1.5 in x 1.7 in. x 0.75 in (3.84 cm x 4.3 cm x 1.9 cm)

Windows 10 64-bit

Linux®

Intel® I225-T1 1-Port 2.5GbE NIC

Connector RJ-45

CablingCat5e (or better) up to 85mControllerIntel® Ethernet I225 ControllerNetwork Transfer Rates2.5GbE, 1GbE, 100MbE, 10MbE

Supported

Data Path Width PCle Gen3.1x1 **Power Requirement** 1.9W (typical)

Power Requirement 1.9W (typical) **Operating Temperature** 32° to 158° F (0°C to 70°C)

Dimensions (HxW) 2.7 in x 2.57 in. (68.7mm x 65.3mm)

Operating System Driver Windows 11 64-Bit

Windows 10 64-bit

Linux®

* Intel® I225-T1 1-Port 2.5GbE NIC with standard height bracket attached

Low-profile bracket
• Product Literature

Intel® Wi-Fi 6E* AX211 802.11ax, BT 5.3, M.2 With Internal Antenna

WLAN Standards 802.11abgn+acR2+axR2(Pre-Standard) MIMO 2x2

High performance, low power dual band Pre-Standard-802.11ax R2 2x2.

both with 160MHz channel support - Wi-Fi 6E

Antenna 2x2 Dual-Band (internal)

Bluetooth Standards 5.2

Operating Temperature 32° to 176° F (0° to 80° C)

InterfaceM.2 CNVio2DimensionsM.2 2230Kit ContentsNot Available

NOTE: The AX211 with internal antenna only support WIFI 6

*Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.



Intel® Wi-Fi 6E* AX211 802.11ax. BT 5.3. M.2 **With External Antenna** **WLAN Standards** 802.11abgn+acR2+axR2(Pre-Standard) MIMO 2x2

High performance, low power dual band Pre-Standard-802.11ax R2 2x2.

both with 160MHz channel support - Wi-Fi 6E

Antenna 2x2 Dual-Band (External)

Bluetooth Standards 5.2

Operating Temperature 32° to 176° F (0° to 80° C)

Interface M.2 CNVio2 **Dimensions** M.2 2230

Kit Contents ANTENNA, External, Dipole, WLAN, WIFI 6E

NOTE: The AX211 with external antenna support WIFI 6E

*Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.

Intel® Wi-Fi 7 BE200

WLAN Standards 802.11abgn+acR2+axR2+be+dehikrv

Antenna 2x2 Dual-Band (External)

Bluetooth Standards

Operating Temperature 32° to 176° F (0° to 80° C)

Interface M.2: PCIe, USB **Dimensions** M.2 2230

Kit Contents ANTENNA, External, Dipole, WLAN, WIFI 7

NOTE: Not available with 12th Gen Intel ADL processors; Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 7 (802.11BE) functionality requires Windows 11 24H2, select Intel® processor, and a Wi-Fi 7 router, sold separately. Wi-Fi 7 is backwards compatible with prior 802.11 specs. Available in countries where Wi-Fi 7 is supported.

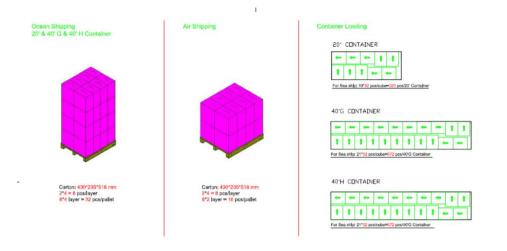
Palletization

Ocean Shipping uses a 20' x 40' x 40' (490mm x 295mm x 518mm) container with 4 layers: 2x4=8 pieces per layer for a total of 32 pieces per pallet

Air shipping uses 490mm x 295mm x 518mm carton with 2 layers; 2x4=8 pieces per layer for a total of 16 pieces per pallet.



Technical Specifications - Networking and Communications



Date of change:	Version History:		Description of change:
March 8, 2022	From v1 to v2	Changed	Format
March 16, 2022	From v2 to v3	Changed	Social and Environmental Responsibility section
May 6, 2022	From v3 to v4	Changed	Processors, Graphics, Networking and Communications sections
June 1, 2022	From v4 to v5	Changed	Operating Systems and SATA Hard Drives sections
June 15, 2022	From v5 to v6	Changed	Networking and Communications section
July 1, 2022	From v6 to v7	Changed	Graphics section
July 8, 2022	From v7 to v8	Changed	System Board section
August 1, 2022	From v8 to v9	Changed	SATA Hard Drives, Other Hardware sections
August 4, 2022	From v9 to v10	Changed	Format
September 1, 2022	From v10 to v11	Changed	Storage / Hard Drives, Graphics, Optical and Removable Storage
			Networking and Communications sections
October 1, 2022	From v11 to v12	Changed	Graphics, Networking and Communications sections
November 1, 2022	From v12 to v13	Changed	Graphics Adapters section
February 6, 2023	From v13 to v14	Changed	Processors section
March 1, 2023	From v14 to v15	Changed	Manageability section
March 30, 2023	From v15 to v16	Changed	Processors section
April 25, 2023	From v16 to v17	Changed	Power Supply, Social and Environmental Responsibility sections
May 1, 2023	From v17 to v18	Changed	Other Hardware section
June 1, 2023	From v18 to v19	Changed	Graphics, Social and Environmental Responsibility, Palletization
			sections
July 1, 2023	From v19 to v20	Changed	Networking and Communications, Other Hardware, HP BIOS sections
July 5, 2023	From v20 to v21	Changed	System Board section
August 1, 2023	From v21 to v22	Changed	Social and Environmental Responsibility section
August 1, 2023	From v22 to v23	Changed	ENVIRONMENTAL DATA section
September 15, 2023	From v23 to v24	Changed	Networking and Communications
October 1, 2023	From v24 to v25	Changed	Graphics, Input Devices sections
November 1, 2023	From v25 to v26	Changed	Graphics, Input Devices sections
December 1, 2023	From v26 to v27	Changed	Graphics, Other Hardware, Social and Environmental Responsibility
			sections
December 11, 2023	From v27 to v28	Changed	Optical and Removable Storage section
December 21, 2023	From v28 to v29	Changed	Graphics section
February 1, 2024	From v29 to v30	Changed	Social and Environmental Responsibility section
March 1, 2024	From v30 to v31	Changed	Graphics, System Configurations, Declared Noise Emissions and
			Networking and Communications sections
March 12, 2024	From v31 to v32	Changed	Processors section
April 1, 2024	From v32 to v33	Changed	Graphics and Other Hardware sections



May 1, 2024	From v33 to v34	Changed	Graphics, Social and Environmental Responsibility sections
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